MUX36xxx 低容量、低リーク電流、36V高精度アナログ・マルチプレクサ

1 特長

- 小さいオン容量
  - MUX36S16: 13.5pF
  - MUX36D08: 8.7pF
- 少ない入力リーク電流: 1pA
- 少ない電荷注入: 0.31pC
- レール・ツー・レール動作
- 広い電源電圧範囲: ±5V ～ ±18V、10V ～ 36V
- 小さいオン抵抗: 125Ω
- 遷移時間: 97ns
- Break-Before-Make の切り替え動作
- EN ピンを V_{DD} に接続可能
- ロジック・レベル: 2V ～ V_{DD}
- 低い消費電流: 45µA
- ESD 保護 (HBM): 2000V
- 業界標準の TSSOP/SOIC パッケージと、小型の WQFN パッケージのオプション

2 アプリケーション

- ファクトリ・オートメーションと産業用プロセス制御
- プログラマブル・ロジック・コントローラ (PLC)
- アナログ入力モジュール
- ATE 試験装置
- デジタル・マルチメータ
- バッテリ・モニタリング・システム

3 概要

MUX36S16およびMUX36D08 (MUX36xxx)は、最新のCMOS (相補型金属酸化膜半導体)高精度アナログ・マルチプレクサ(MUX)です。MUX36S16は16:1シングルエンド・チャネル、MUX36D08は差動8:1またはデュアル8:1シングルエンド・チャネルを提供します。MUX36S16およびMUX36D08は、デュアル電源(±5V～±18V)でも単電源(10V～36V)でも正常に動作します。また、対称電源(V_{DD} = 12V、V_{SS} = –12Vなど)でも、非対称電源(V_{DD} = 12V、V_{SS} = –5Vなど)でも正常に動作します。すべてのデジタル入力は、TTL (トランジスタ-トランジスタ・ロジック)互換しきい値を備えており、有効電源電圧範囲内で動作するときにTTLおよびCMOS両方のロジック互換性を提供します。

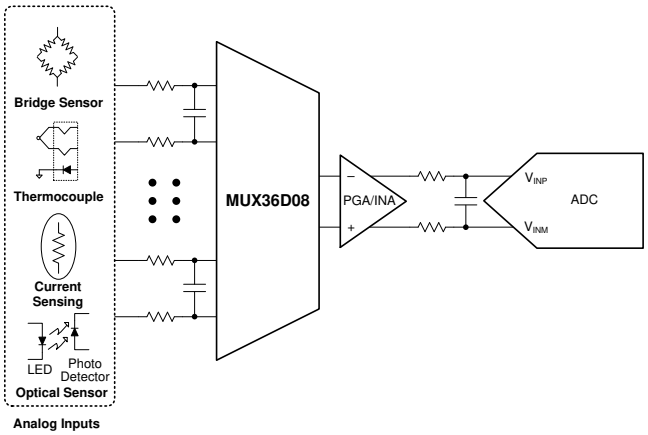
MUX36S16およびMUX36D08のオン/オフ・リーク電流は非常に低いため、入力インピーダンスの高い信号源からの信号を最小限の誤差でスイッチング可能です。45µAの低い消費電流により、低消費電力が重要なアプリケーションで使用できます。

製品情報(1)

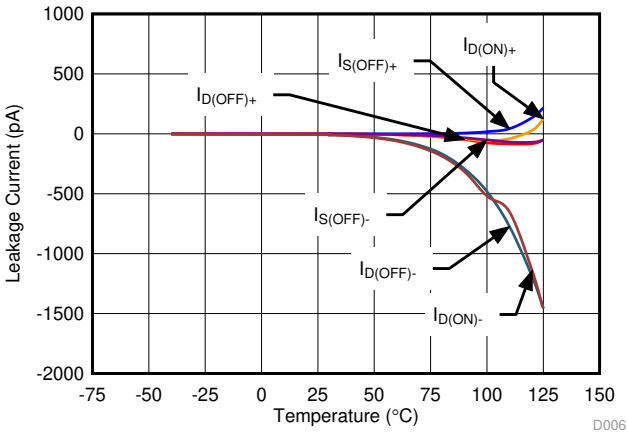
型番	パッケージ	本体サイズ(公称)
MUX36S16 MUX36D08	TSSOP (28)	9.70mm×6.40mm
	SOIC (28)	17.9mm×7.50mm
	WQFN (RTV) (32)	5.00mm×5.00mm
	WQFN (RSN) (32)	4.00mm×4.00mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にあるパッケージ・オプションについての付録を参照してください。

概略回路図



リーク電流と温度



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4 改訂履歴

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

Revision B (April 2018) から **Revision C** に変更 **Page**

- Added BW, THD+N, and C_{IN} rows to the *Electrical Characteristics: Dual Supply* ... 9
- Changed V_{DD} and V_{SS} supply current MAX values for ±15V supplies in *Electrical Characteristics: Dual Supply* ... 9
- Changed V_{DD} and V_{SS} supply current MAX values for 12V supplies in *Electrical Characteristics: Single Supply* ... 11

Revision A (November 2017) から **Revision B** に変更 **Page**

- 「特長」に WQFN パッケージ・オプションを追加 ... 1
- 「*製品情報*」にWQFNパッケージ・オプションを 追加 ... 1
- Added pinout information for WQFN packages ... 3
- Added data for WQFN packages to *Thermal Information* ... 8

2016年11月 発行のものから更新 **Page**

- 「*特長*」一覧で遷移時間を 85ns から 97ns (標準値) に 変更 ... 1
- 「*特長*」および「*製品情報*」にSOICパッケージを 追加 ... 1
- Added the DW (SOIC) package to the *Pin Configuration and Functions* section ... 3
- Added SOIC package to the *Thermal Information* table ... 8
- Changed Transition time Typ value From 85: ns To: 97ns for ±15 V supplies in the *Electrical Characteristics: Dual Supply* table ... 9
- Added additional specifications for the SOIC packages (Q_J, Off-isolation, and channel-to-channel crosstalk) for ±15 V supplies in *Electrical Characteristics: Dual Supply* ... 9
- Changed Transition time Typ value From: 91 To: 102 ns for 12 V supply in the *Electrical Characteristics: Single Supply* table ... 11
- Added additional specifications for the SOIC packages (Q_J, Off-isolation, and channel-to-channel crosstalk) for 12 V supply in *Electrical Characteristics: Single Supply* ... 11

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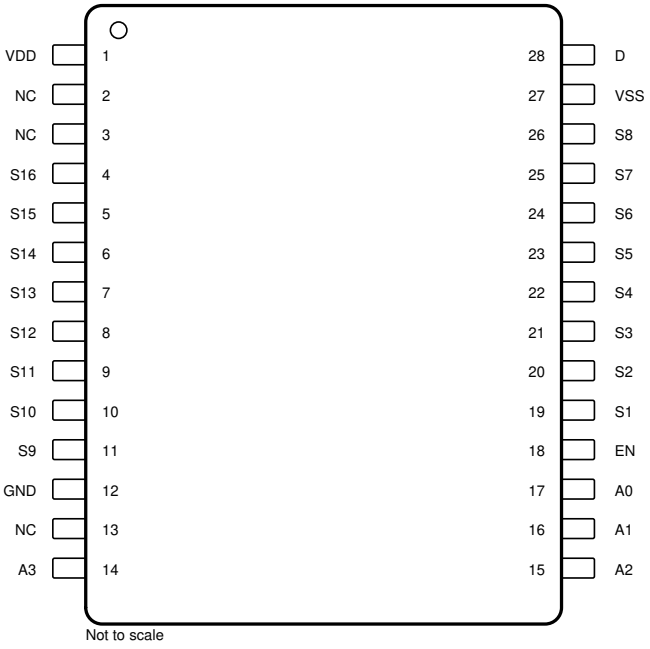
5 Pin Configuration and Functions

MUX36S16: DW and PW Package
28-Pin SOIC and TSSOP
Top View



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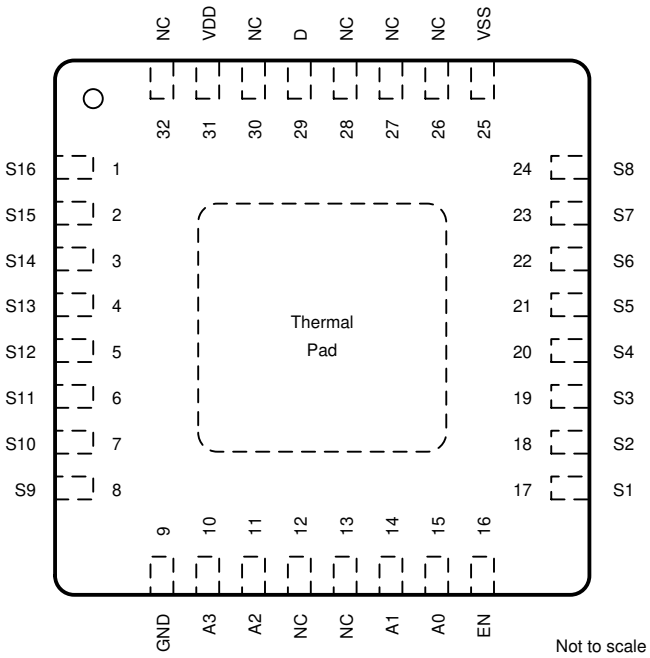
MUX36S16: RTV and RSN Package
32-Pin WQFN
Top View



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Pin Functions, MUX36S16

PIN			FUNCTION	DESCRIPTION
NAME	TSSOP/ SOIC	WQFN		
A0	17	15	Digital input	Address line 0
A1	16	14	Digital input	Address line 1
A2	15	11	Digital input	Address line 2
A3	14	10	Digital input	Address line 3
D	28	29	Analog input or output	Drain pin. Can be an input or output.
EN	18	16	Digital input	Active high digital input. When this pin is low, all switches are turned off. When this pin is high, the A[3:0] logic inputs determine which switch is turned on.
GND	12	9	Power supply	Ground (0 V) reference
NC	2, 3, 13	12, 13, 26, 27, 28, 30, 32	No connect	Do not connect
S1	19	17	Analog input or output	Source pin 1. Can be an input or output.
S2	20	18	Analog input or output	Source pin 2. Can be an input or output.
S3	21	19	Analog input or output	Source pin 3. Can be an input or output.
S4	22	20	Analog input or output	Source pin 4. Can be an input or output.
S5	23	21	Analog input or output	Source pin 5. Can be an input or output.
S6	24	22	Analog input or output	Source pin 6. Can be an input or output.
S7	25	23	Analog input or output	Source pin 7. Can be an input or output.
S8	26	24	Analog input or output	Source pin 8. Can be an input or output.
S9	11	8	Analog input or output	Source pin 9. Can be an input or output.
S10	10	7	Analog input or output	Source pin 10. Can be an input or output.

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Pin Functions, MUX36S16 (continued)

PIN			FUNCTION	DESCRIPTION
NAME	TSSOP/ SOIC	WQFN		
S11	9	6	Analog input or output	Source pin 11. Can be an input or output.
S12	8	5	Analog input or output	Source pin 12. Can be an input or output.
S13	7	4	Analog input or output	Source pin 13. Can be an input or output.
S14	6	3	Analog input or output	Source pin 14. Can be an input or output.
S15	5	2	Analog input or output	Source pin 15. Can be an input or output.
S16	4	1	Analog input or output	Source pin 16. Can be an input or output.
VDD	1	31	Power supply	Positive power supply. This pin is the most positive power-supply potential. For reliable operation, connect a decoupling capacitor ranging from 0.1 µF to 10 µF between V_{DD} and GND.
VSS	27	25	Power supply	Negative power supply. This pin is the most negative power-supply potential. In single-supply applications, this pin can be connected to ground. For reliable operation, connect a decoupling capacitor ranging from 0.1 µF to 10 µF between V_{SS} and GND.

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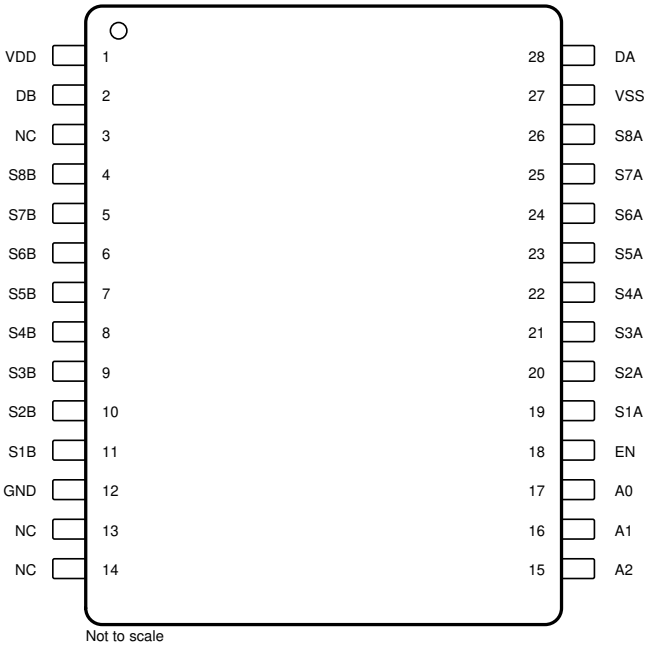
MUX36D08: DW and PW Package
28-Pin SOIC and TSSOP
Top View



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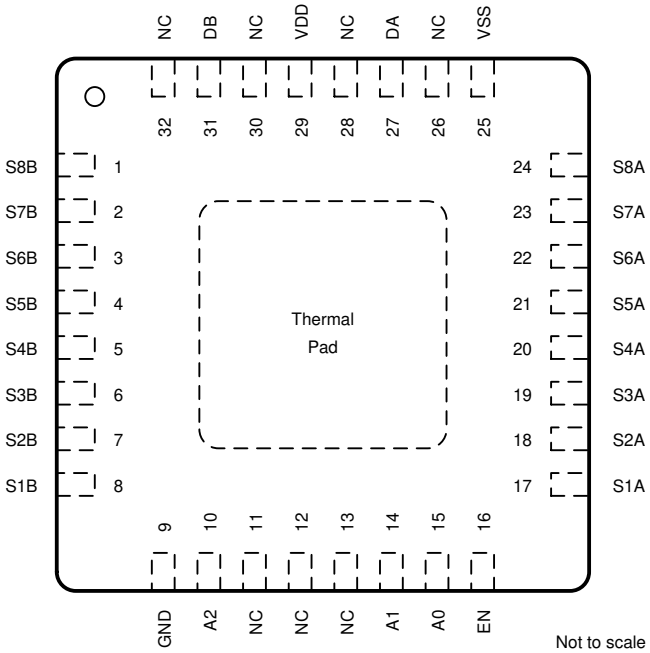
MUX36D08: RTV and RSN Package
32-Pin WQFN
Top View



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Pin Functions: MUX36D08

PIN			FUNCTION	DESCRIPTION
NAME	TSSOP/ SOIC	WQFN		
A0	17	15	Digital input	Address line 0
A1	16	14	Digital input	Address line 1
A2	15	10	Digital input	Address line 2
DA	28	27	Analog input or output	Drain pin A. Can be an input or output.
DB	2	31	Analog input or output	Drain pin B. Can be an input or output.
EN	18	16	Digital input	Active high digital input. When this pin is low, all switches are turned off. When this pin is high, the A[2:0] logic inputs determine which pair of switches is turned on.
GND	12	9	Power supply	Ground (0 V) reference
NC	3, 13, 14	11, 12, 13, 26, 28, 30, 32	No connect	Do not connect
S1A	19	17	Analog input or output	Source pin 1A. Can be an input or output.
S2A	20	18	Analog input or output	Source pin 2A. Can be an input or output.
S3A	21	19	Analog input or output	Source pin 3A. Can be an input or output.
S4A	22	20	Analog input or output	Source pin 4A. Can be an input or output.
S5A	23	21	Analog input or output	Source pin 5A. Can be an input or output.
S6A	24	22	Analog input or output	Source pin 6A. Can be an input or output.
S7A	25	23	Analog input or output	Source pin 7A. Can be an input or output.
S8A	26	24	Analog input or output	Source pin 8A. Can be an input or output.
S1B	11	8	Analog input or output	Source pin 1B. Can be an input or output.
S2B	10	7	Analog input or output	Source pin 2B. Can be an input or output.
S3B	9	6	Analog input or output	Source pin 3B. Can be an input or output.

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Pin Functions: MUX36D08 (continued)

PIN			FUNCTION	DESCRIPTION
NAME	TSSOP/ SOIC	WQFN		
S4B	8	5	Analog input or output	Source pin 4B. Can be an input or output.
S5B	7	4	Analog input or output	Source pin 5B. Can be an input or output.
S6B	6	3	Analog input or output	Source pin 6B. Can be an input or output.
S7B	5	2	Analog input or output	Source pin 7B. Can be an input or output.
S8B	4	1	Analog input or output	Source pin 8B. Can be an input or output.
VDD	1	29	Power supply	Positive power supply. This pin is the most positive power supply potential. For reliable operation, connect a decoupling capacitor ranging from 0.1 µF to 10 µF between V_{DD} and GND.
VSS	27	25	Power supply	Negative power supply. This pin is the most negative power supply potential. In single-supply applications, this pin can be connected to ground. For reliable operation, connect a decoupling capacitor ranging from 0.1 µF to 10 µF between V_{SS} and GND.

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6 Specifications

6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)(1)

			MIN	MAX	UNIT
Voltage	Supply	V_{DD}	–0.3	40	V
		V_{SS}	–40	0.3	
		$V_{DD} – V_{SS}$		40	
	Digital pins(2): EN, A0, A1, A2, A3		$V_{SS} – 0.3$	$V_{DD} + 0.3$	
	Analog pins(2): Sx, SxA, SxB, D, DA, DB		$V_{SS} – 2$	$V_{DD} + 2$	
Current(3)			–30	30	mA
Temperature	Operating, T_A		–55	150	°C
	Junction, T_J			150	
	Storage, T_{stg}		–65	150	

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) Voltage limits are valid if current is limited to ±30 mA.
(3) Only one pin at a time.

6.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001(1)	2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101(2)	500	

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V_{DD}(1)	Positive power-supply voltage	Dual supply	5		18	V
		Single supply	10		36	
V_{SS}(2)	Negative power-supply voltage (dual supply)		–5		–18	V
$V_{DD} – V_{SS}$	Supply voltage		10		36	V
V_S	Source pins voltage(3)		V_{SS}		V_{DD}	V
V_D	Drain pins voltage		V_{SS}		V_{DD}	V
V_{EN}	Enable pin voltage		V_{SS}		V_{DD}	V
V_A	Address pins voltage		V_{SS}		V_{DD}	V
I_{CH}	Channel current (T_A = 25°C)		–25		25	mA
T_A	Operating temperature		–40		125	°C

(1) When V_{SS} = 0 V, V_{DD} can range from 10 V to 36 V.
(2) V_{DD} and V_{SS} can be any value as long as 10 V ≤ ($V_{DD} – V_{SS}$) ≤ 36 V.
(3) V_S is the voltage on all the S pins.

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6.4 Thermal Information

THERMAL METRIC(1)		MUX36S16/ MUX36D08				UNIT
		PW (TSSOP)	DW (SOIC)	RTV (WQFN)	RSN (WQFN)	
		28 PINS	28 PINS	32 PINS	32 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	79.8	53.6	33.0	33.7	°C/W
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	24.0	30.1	20.8	26.5	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	37.6	28.5	13.9	13.4	°C/W
ψ_{JT}	Junction-to-top characterization parameter	1.2	9.0	0.3	0.3	°C/W
ψ_{JB}	Junction-to-board characterization parameter	37.1	28.4	13.8	13.4	°C/W
$R_{\theta JC(bot)}$	Junction-to-case (bottom) thermal resistance	N/A	N/A	4.1	4.1	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

6.5 Electrical Characteristics: Dual Supply

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ANALOG SWITCH							
	Analog signal range	T_A = –40°C to +125°C		V_{SS}		V_{DD}	V
R_{ON}	On-resistance	V_S = 0 V, I_S = –1 mA			125	170	Ω
		V_S = ±10 V, I_S = –1 mA			145	200	
			T_A = –40°C to +85°C			230	
			T_A = –40°C to +125°C			250	
ΔR_{ON}	On-resistance mismatch between channels	V_S = ±10 V, I_S = –1 mA			6	9	Ω
			T_A = –40°C to +85°C			14	
			T_A = –40°C to +125°C			16	
R_{FLAT}	On-resistance flatness	V_S = 10 V, 0 V, –10 V			20	45	Ω
			T_A = –40°C to +85°C			53	
			T_A = –40°C to +125°C			58	
	On-resistance drift	V_S = 0 V			0.62		Ω/°C
$I_{S(OFF)}$	Input leakage current	Switch state is off, V_S = ±10 V, V_D = ±10 V(1)		–0.04	0.001	0.04	nA
			T_A = –40°C to +85°C	–0.15		0.15	
			T_A = –40°C to +125°C	–1.2		1.2	
$I_{D(OFF)}$	Output off-leakage current	Switch state is off, V_S = ±10 V, V_D = ±10 V(1)		–0.15	0.01	0.15	nA
			T_A = -40°C to +85°C	–1		1	
			T_A = -40°C to +125°C	–4.5		4.5	
$I_{D(ON)}$	Output on-leakage current	Switch state is on, V_D = ±10 V, V_S = floating		–0.2	0.01	0.2	nA
			T_A = –40°C to +85°C	–1		1	
			T_A = –40°C to +125°C	–5.3		5.3	
$I_{DL(ON)}$	Differential on-leakage current	Switch state is on, V_{DA} = V_{DB} = ±10 V, V_S = floating		–15	3	15	pA
			T_A = –40°C to +85°C	–100		100	
			T_A = –40°C to +125°C	–500		500	
LOGIC INPUT							
V_{IH}	Logic voltage high			2			V
V_{IL}	Logic voltage low					0.8	V
I_D	Input current					0.1	µA

(1) When V_S is positive, V_D is negative, and vice versa.

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Electrical Characteristics: Dual Supply (continued)

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
SWITCH DYNAMICS(2)								
t_{ON}	Enable turn-on time	V_S = ±10 V, R_L = 300 Ω, C_L= 35 pF				82	136	ns
			T_A = –40°C to +85°C				145	
			T_A = –40°C to +125°C				151	
t_{OFF}	Enable turn-off time	V_S = ±10 V, R_L = 300 Ω, C_L= 35 pF				63	78	ns
			T_A = –40°C to +85°C				89	
			T_A = –40°C to +125°C				97	
t_t	Transition time	V_S = 10 V, R_L = 300 Ω, C_L= 35 pF,				97	143	ns
			T_A = –40°C to +85°C				151	
			T_A = –40°C to +125°C				157	
t_{BBM}	Break-before-make time delay	V_S = 10 V, R_L = 300 Ω, C_L= 35 pF, T_A = –40°C to +125°C			30	54		ns
Q_J	Charge injection	C_L = 1 nF, R_S = 0 Ω	V_S = 0 V	TSSOP package		0.31		pC
				SOIC package		0.67		
			V_S = –15 V to +15 V	TSSOP package		±0.9		
				SOIC package		±1.1		
	Off-isolation	R_L = 50 Ω, V_S = 1 V_{RMS}, f = 1 MHz	Nonadjacent channel to D, DA, DB	TSSOP package		–98		dB
				SOIC package		–94		
			Adjacent channel to D, DA, DB	TSSOP package		–94		
				SOIC package		–88		
	Channel-to-channel crosstalk	R_L = 50 Ω, V_S = 1 V_{RMS}, f = 1 MHz	Nonadjacent channels	TSSOP package		–100		dB
				SOIC package		–96		
			Adjacent channels	TSSOP package		–88		
				SOIC package		–83		
BW	–3dB Bandwidth	V_S = 1 V_{RMS}, R_L = 50 Ω , C_L = 5 pF	MUX36S16			260		dB
			MUX36D08			430		
THD + N	Total harmonic distortion plus noise	V_S = 0 V or V_{DD}, R_L = 600 Ω , C_L = 50 pF, f = 20Hz to 20kHz				0.09%		
C_{IN}	Digital input capacitance	V_{IN} = 0 V or V_{DD}				1.1		pF
$C_{S(OFF)}$	Input off-capacitance	f = 1 MHz, V_S = 0 V				2.1	3	pF
$C_{D(OFF)}$	Output off-capacitance	f = 1 MHz, V_S = 0 V	MUX36S16			11.1	12.2	pF
			MUX36D08			6.4	7.5	
$C_{S(ON)}$, $C_{D(ON)}$	Output on-capacitance	f = 1 MHz, V_S = 0 V	MUX36S16			13.5	15	pF
			MUX36D08			8.7	10.2	
POWER SUPPLY								
	V_{DD} supply current	All V_A = 0 V or 3.3 V, V_S = 0 V, V_{EN} = 3.3 V,				45	59	µA
			T_A = –40°C to +85°C				62	
			T_A = –40°C to +125°C				69	
	V_{SS} supply current	All V_A = 0 V or 3.3 V, V_S = 0 V, V_{EN} = 3.3 V,				26	33	µA
			T_A = –40°C to +85°C				36	
			T_A = –40°C to +125°C				43	

(2) Specified by design; not subject to production testing.

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6.6 Electrical Characteristics: Single Supply

at T_A = 25°C, V_{DD} = 12 V, and V_{SS} = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
ANALOG SWITCH							
	Analog signal range	T_A = –40°C to +125°C		V_{SS}		V_{DD}	V
R_{ON}	On-resistance	V_S = 10 V, I_S = –1 mA			235	340	Ω
			T_A = –40°C to +85°C			390	
			T_A = –40°C to +125°C			430	
ΔR_{ON}	On-resistance match	V_S = 10 V, I_S = –1 mA			7	20	Ω
			T_A = –40°C to +85°C			35	
			T_A = –40°C to +125°C			40	
	On-resistance drift	V_S = 10 V			1.07		Ω/°C
$I_{S(OFF)}$	Input leakage current	Switch state is off, V_S = 1 V and V_D = 10 V, or V_S = 10 V and V_D = 1 V(1)		–0.04	0.001	0.04	nA
			T_A = –40°C to +85°C	–0.15		0.15	
			T_A = –40°C to +125°C	–1.2		1.2	
$I_{D(OFF)}$	Output off leakage current	Switch state is off, V_S = 1 V and V_D = 10 V, or V_S = 10 V and V_D = 1 V(1)		–0.15	0.01	0.15	nA
			T_A = –40°C to +85°C	–0.75		0.75	
			T_A = –40°C to +125°C	–2.4		2.4	
$I_{D(ON)}$	Output on leakage current	Switch state is on, V_D = 1 V and 10 V, V_S = floating		–0.15	0.01	0.15	nA
			T_A = –40°C to +85°C	–0.75		0.75	
			T_A = –40°C to +125°C	–2.5		2.5	
$I_{DL(ON)}$	Differential on-leakage current	Switch state is on, V_{DA} = V_{DB} = 1 V and 10 V, V_S = floating		–15	3	15	pA
			T_A = –40°C to +85°C	–100		100	
			T_A = –40°C to +125°C	–500		500	
LOGIC INPUT							
V_{IH}	Logic voltage high			2.0			V
V_{IL}	Logic voltage low					0.8	V
I_D	Input current					0.1	µA

(1) When V_S is 1 V, V_D is 10 V, and vice versa.

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Electrical Characteristics: Single Supply (continued)

at T_A = 25°C, V_{DD} = 12 V, and V_{SS} = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP	MAX	UNIT
SWITCH DYNAMIC CHARACTERISTICS(2)								
t_{ON}	Enable turn-on time	V_S = 8 V, R_L = 300 Ω, C_L= 35 pF				90	145	ns
			T_A = –40°C to +85°C				145	
			T_A = –40°C to +125°C				149	
t_{OFF}	Enable turn-off time	V_S = 8 V, R_L = 300 Ω, C_L= 35 pF				66	84	ns
			T_A = –40°C to +85°C				94	
			T_A = –40°C to +125°C				102	
t_t	Transition time	V_S = 8 V, C_L= 35 pF				107	147	ns
		V_S = 8 V, R_L = 300 Ω, C_L= 35 pF,	T_A = –40°C to +85°C				153	
		V_S = 8 V, R_L = 300 Ω, C_L= 35 pF,	T_A = –40°C to +125°C				155	
t_{BBM}	Break-before-make time delay	V_S = 8 V, R_L = 300 Ω, C_L= 35 pF, T_A = –40°C to +125°C			30	54		ns
Q_J	Charge injection	C_L = 1 nF, R_S = 0 Ω	V_S = 6 V	TSSOP package		0.12		pC
				SOIC package		0.38		
			V_S = 0 V to 12 V	TSSOP		±0.17		
				SOIC package		±0.48		
	Off-isolation	R_L = 50 Ω, V_S = 1 V_{RMS}, f = 1 MHz	Nonadjacent channel to D, DA, DB	TSSOP package		–97		dB
				SOIC package		–94		
			Adjacent channel to D, DA, DB	TSSOP package		–94		
				SOIC package		–88		
	Channel-to-channel crosstalk	R_L = 50 Ω, V_S = 1 V_{RMS}, f = 1 MHz	Nonadjacent channels	TSSOP package		–100		dB
				SOIC package		–99		
			Adjacent channels	TSSOP		-88		
				SOIC package		-83		
$C_{S(OFF)}$	Input off-capacitance	f = 1 MHz, V_S = 6 V				2.4	3.4	pF
$C_{D(OFF)}$	Output off-capacitance	f = 1 MHz, V_S = 6 V	MUX36S16			14	15.4	pF
			MUX36D08			7.8	9.1	
$C_{S(ON)}$, $C_{D(ON)}$	Output on-capacitance	f = 1 MHz, V_S = 6 V	MUX36S16			16.2	18	pF
			MUX36D08			9.9	11.6	
POWER SUPPLY								
	V_{DD} supply current	All V_A = 0 V or 3.3 V, V_S= 0 V, V_{EN} = 3.3 V				41	59	µA
			T_A = –40°C to +85°C				56	
			T_A = –40°C to +125°C				62	
	V_{SS} supply current	All V_A = 0 V or 3.3 V, V_S = 0 V, V_{EN} = 3.3 V				22	29	µA
			T_A = –40°C to +85°C				31	
			T_A = –40°C to +125°C				37	

(2) Specified by design, not subject to production test.

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6.7 Typical Characteristics

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)

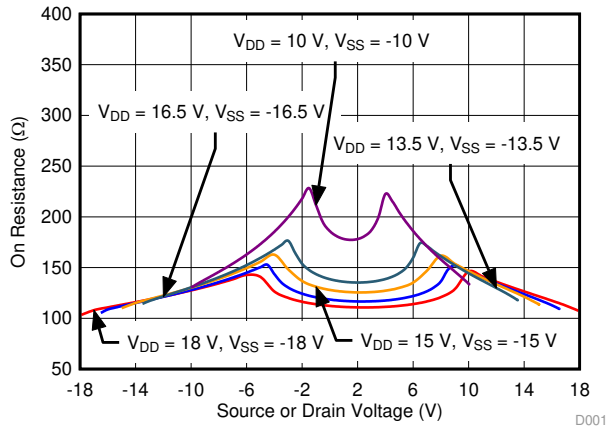
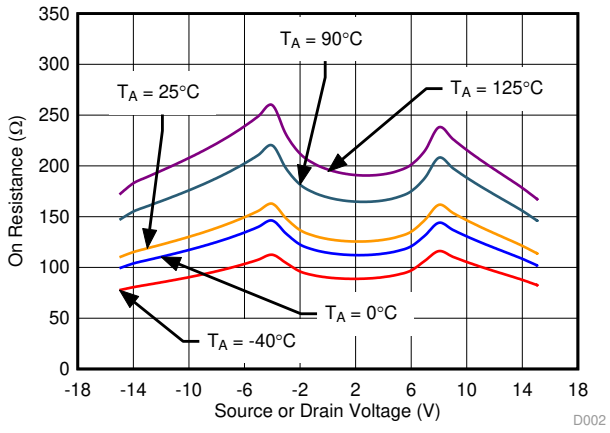


図 1. On-Resistance vs Source or Drain Voltage



V_{DD} = 15 V, V_{SS} = –15 V

図 2. On-Resistance vs Source or Drain Voltage

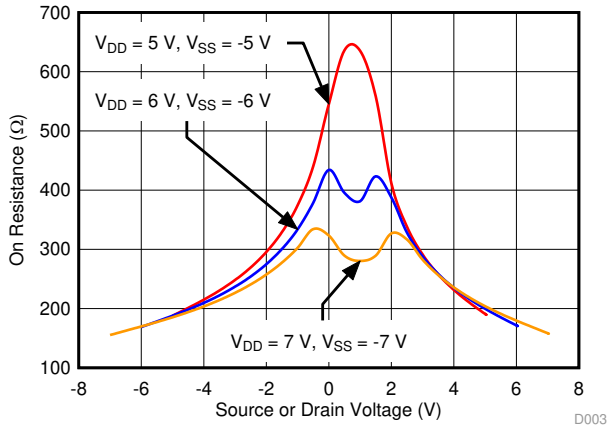
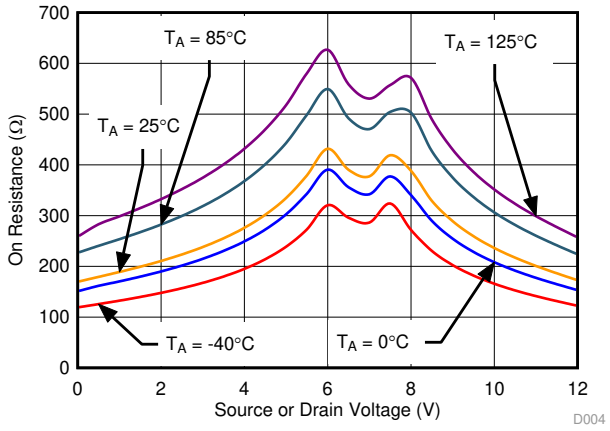


図 3. On-Resistance vs Source or Drain Voltage



V_{DD} = 12 V, V_{SS} = 0 V

図 4. On-Resistance vs Source or Drain Voltage

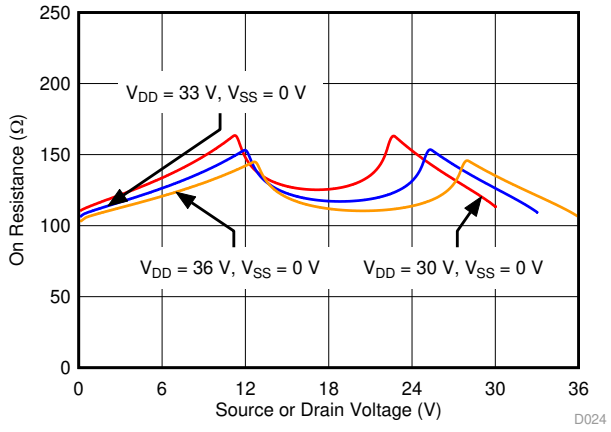


図 5. On-Resistance vs Source or Drain Voltage

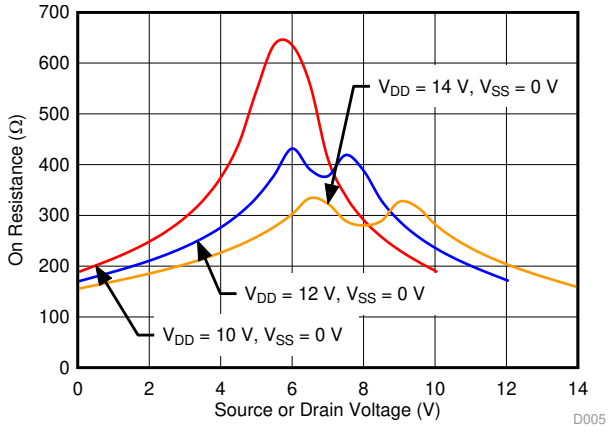


図 6. On-Resistance vs Source or Drain Voltage

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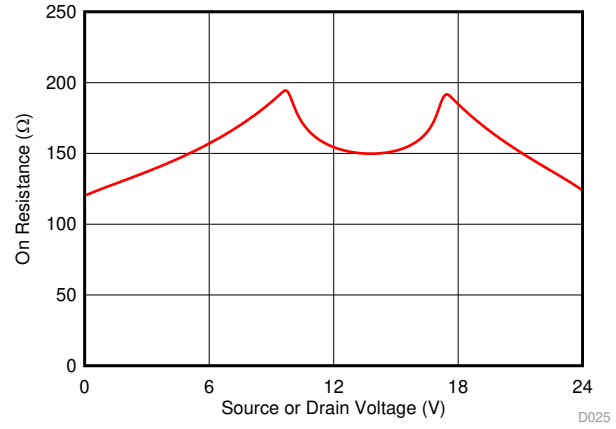
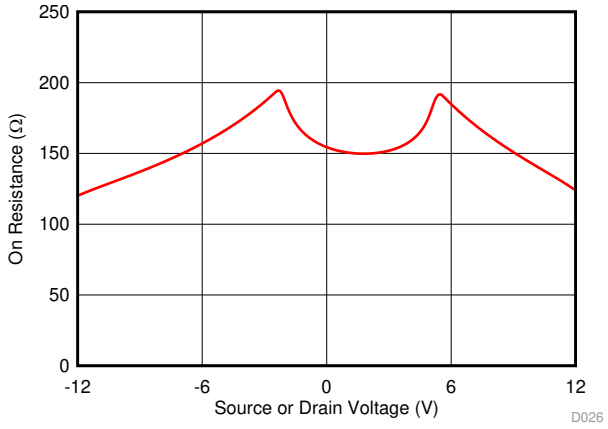
Typical Characteristics (continued)

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)



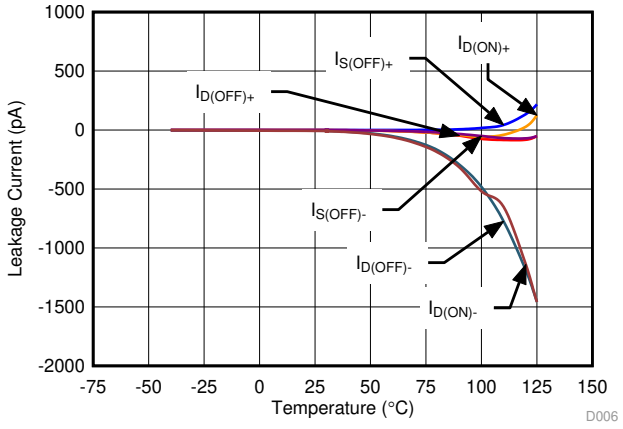
V_{DD} = 24 V, V_{SS} = 0 V

図 7. On-Resistance vs Source or Drain Voltage



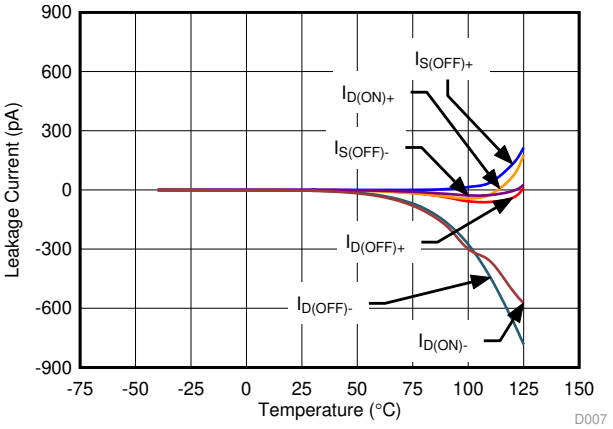
V_{DD} = 12 V, V_{SS} = –12 V

図 8. On-Resistance vs Source or Drain Voltage



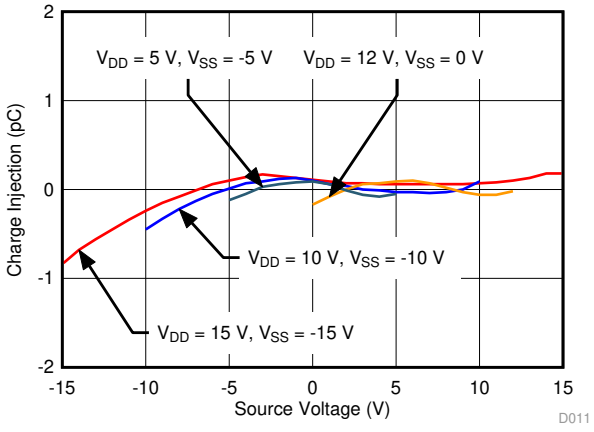
V_{DD} = 15 V, V_{SS} = –15 V

図 9. Leakage Current vs Temperature



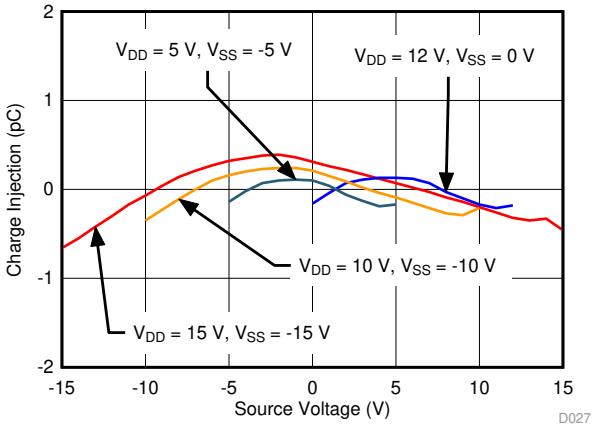
V_{DD} = 12 V, V_{SS} = 0 V

図 10. Leakage Current vs Temperature



MUX36S16, source-to-drain

図 11. Charge Injection vs Source Voltage

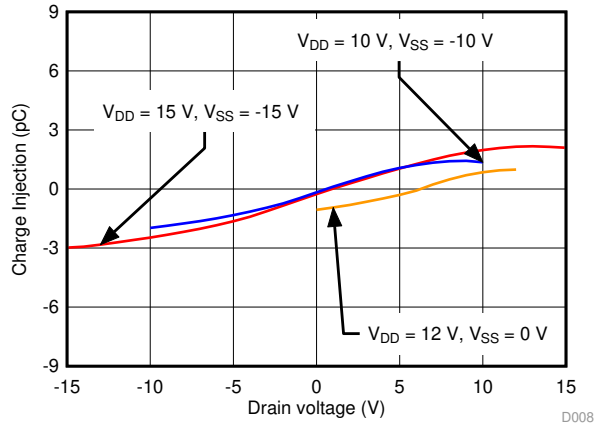


MUX36D08, source-to-drain

図 12. Charge Injection vs Source Voltage

Typical Characteristics (continued)

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)



Drain-to-source

図 13. Charge Injection vs Drain Voltage

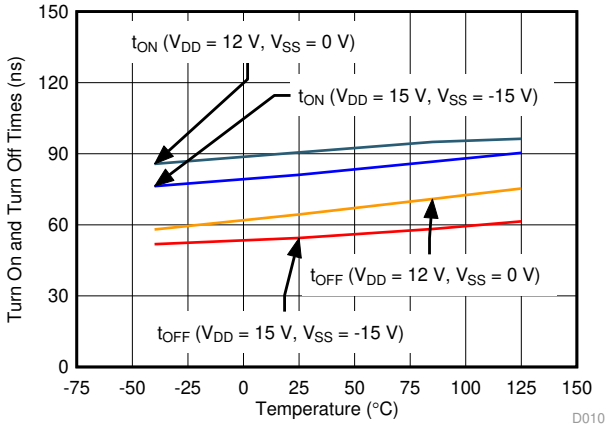


図 14. Turn-On and Turn-Off Times vs Temperature

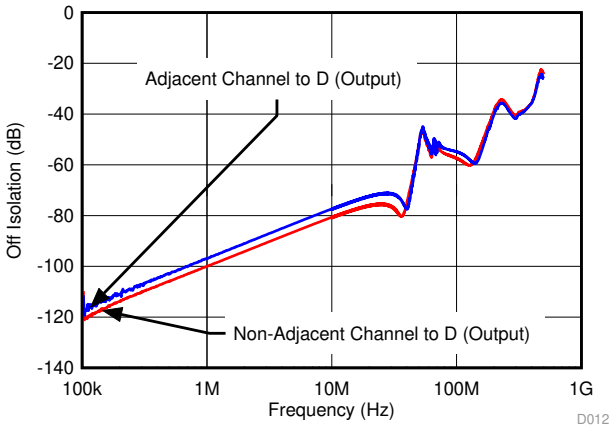


図 15. Off Isolation vs Frequency

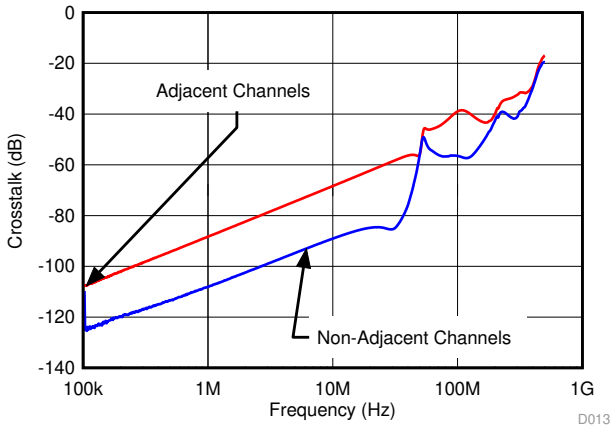


図 16. Crosstalk vs Frequency

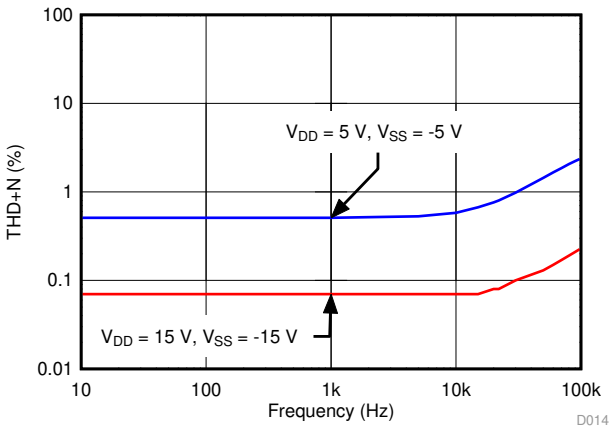


図 17. THD+N vs Frequency

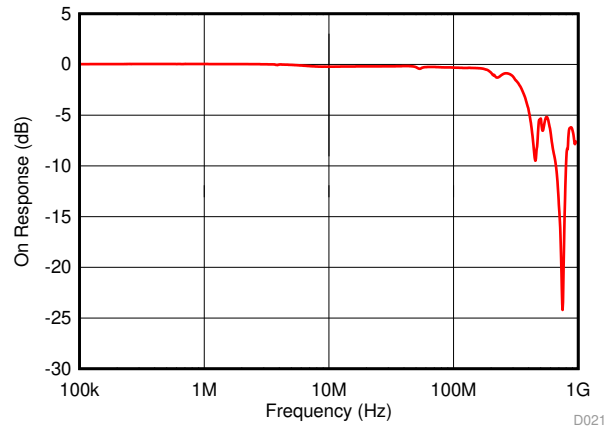


図 18. On Response vs Frequency

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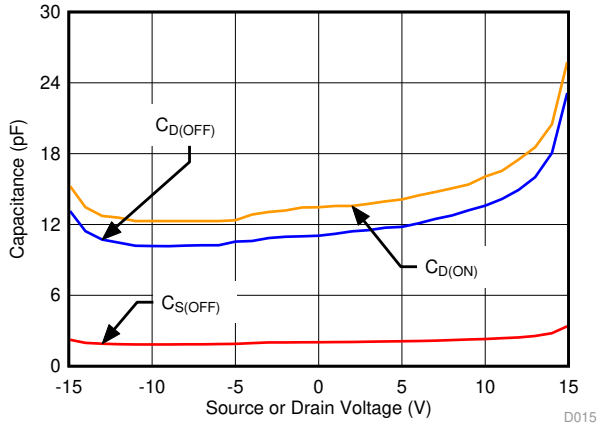
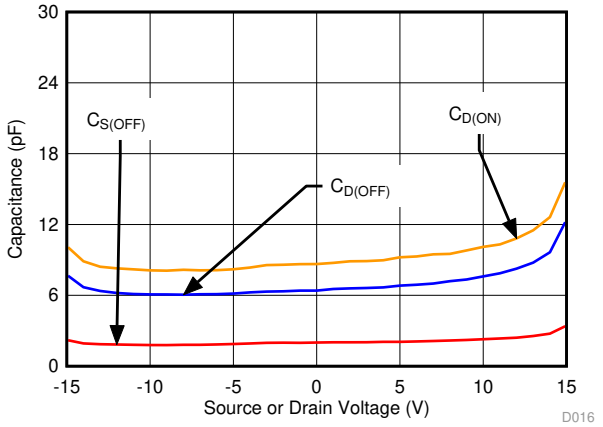
Typical Characteristics (continued)

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)



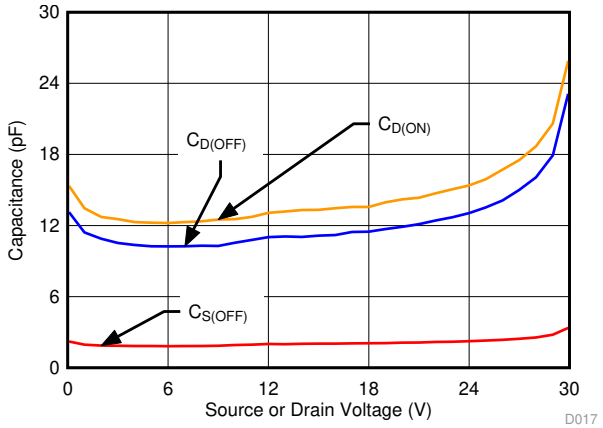
MUX36S16, V_{DD} = 15 V, V_{SS} = –15 V

図 19. Capacitance vs Source Voltage



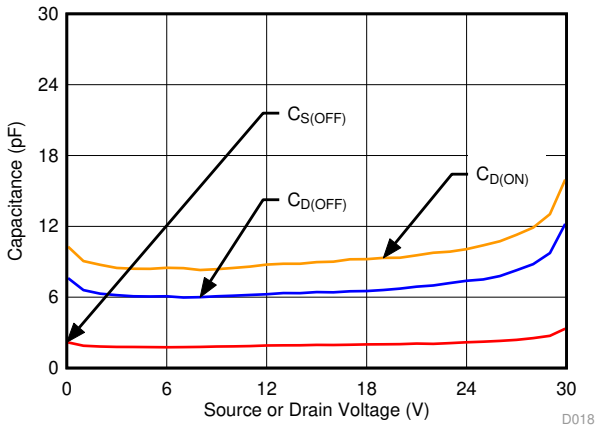
MUX36D08, V_{DD} = 15 V, V_{SS} = –15 V

図 20. Capacitance vs Source Voltage



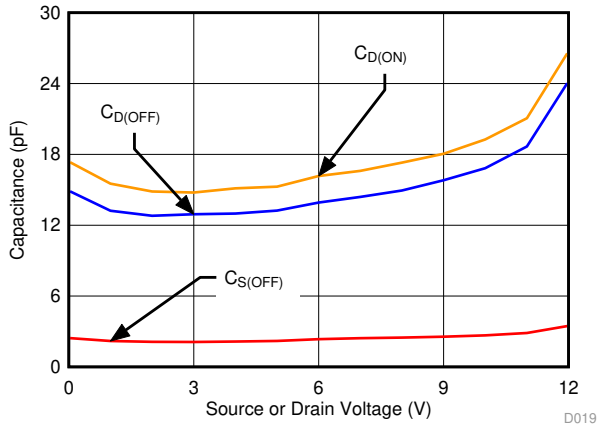
MUX36S16, V_{DD} = 30 V, V_{SS} = 0 V

図 21. Capacitance vs Source Voltage



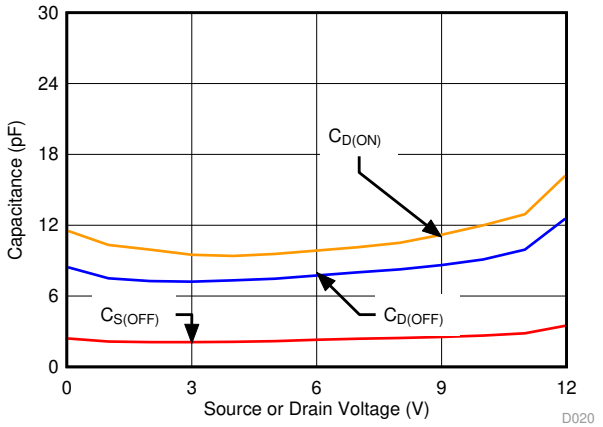
MUX36D08, V_{DD} = 30 V, V_{SS} = 0 V

図 22. Capacitance vs Source Voltage



MUX36S16, V_{DD} = 12 V, V_{SS} = 0 V

図 23. Capacitance vs Source Voltage



MUX36D08, V_{DD} = 12 V, V_{SS} = 0 V

図 24. Capacitance vs Source Voltage

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Typical Characteristics (continued)

at T_A = 25°C, V_{DD} = 15 V, and V_{SS} = –15 V (unless otherwise noted)

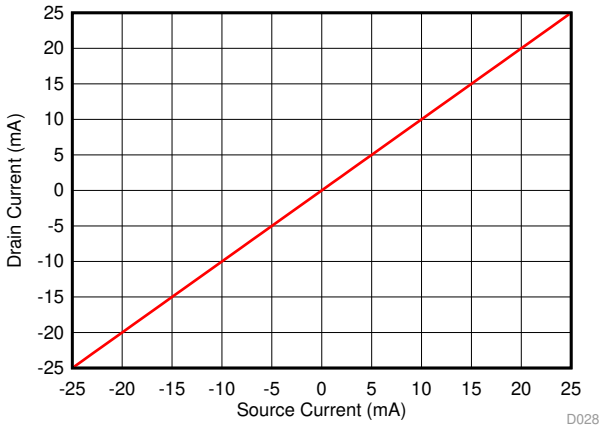

図 25. Source Current vs Drain Current

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7 Parameter Measurement Information

7.1 Truth Tables

表 1. MUX36S16

EN	A3	A2	A1	A0	ON-CHANNEL
0	X(1)	X(1)	X(1)	X(1)	All channels are off
1	0	0	0	0	Channel 1
1	0	0	0	1	Channel 2
1	0	0	1	0	Channel 3
1	0	0	1	1	Channel 4
1	0	1	0	0	Channel 5
1	0	1	0	1	Channel 6
1	0	1	1	0	Channel 7
1	0	1	1	1	Channel 8
1	1	0	0	0	Channel 9
1	1	0	0	1	Channel 10
1	1	0	1	0	Channel 11
1	1	0	1	1	Channel 12
1	1	1	0	0	Channel 13
1	1	1	0	1	Channel 14
1	1	1	1	0	Channel 15
1	1	1	1	1	Channel 16

(1) X denotes *don't care*..

表 2. MUX36D08

EN	A2	A1	A0	ON-CHANNEL
0	X(1)	X(1)	X(1)	All channels are off
1	0	0	0	Channels 1A and 1B
1	0	0	1	Channels 2A and 2B
1	0	1	0	Channels 3A and 3B
1	0	1	1	Channels 4A and 4B
1	1	0	0	Channels 5A and 5B
1	1	0	1	Channels 6A and 6B
1	1	1	0	Channels 7A and 7B
1	1	1	1	Channels 8A and 8B

(1) X denotes *don't care*.

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7.1.1 On-Resistance

The on-resistance of the MUX36xxx is the ohmic resistance across the source (Sx, SxA, or SxB) and drain (D, DA, or DB) pins of the device. The on-resistance varies with input voltage and supply voltage. The symbol R_{ON} is used to denote on-resistance. The measurement setup used to measure R_{ON} is shown in 図 26. Voltage (V) and current (I_{CH}) are measured using this setup, and R_{ON} is computed as shown in 式 1:

$$R_{ON} = V / I_{CH} \quad (1)$$

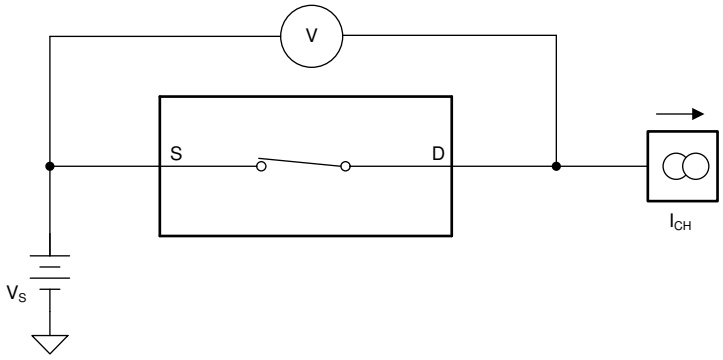

図 26. On-Resistance Measurement Setup

7.1.2 Off Leakage

There are two types of leakage currents associated with a switch during the OFF state:

1. Source off-leakage current
2. Drain off-leakage current

Source leakage current is defined as the leakage current flowing into or out of the source pin when the switch is off. This current is denoted by the symbol $I_{S(OFF)}$.

Drain leakage current is defined as the leakage current flowing into or out of the drain pin when the switch is off. This current is denoted by the symbol $I_{D(OFF)}$.

The setup used to measure both off-leakage currents is shown in 図 27

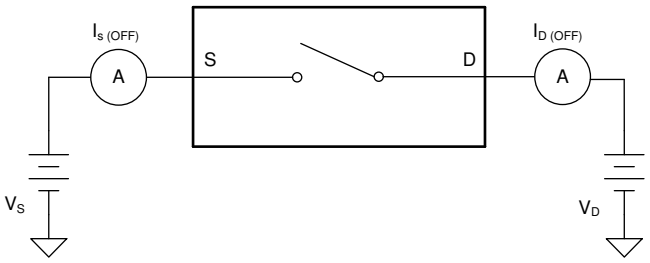

図 27. Off-Leakage Measurement Setup

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7.1.3 On-Leakage Current

On-leakage current is defined as the leakage current that flows into or out of the drain pin when the switch is in the ON state. The source pin is left floating during the measurement. 図 28 shows the circuit used for measuring the on-leakage current, denoted by $I_{D(ON)}$.

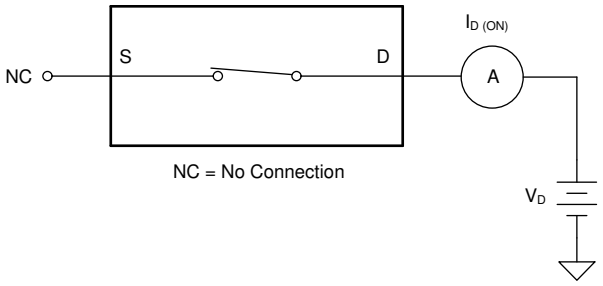

図 28. On-Leakage Measurement Setup

7.1.4 Differential On-Leakage Current

In case of a differential signal, the on-leakage current is defined as the differential leakage current that flows into, or out of, the drain pins when the switches are in the ON state. The source pins are left floating during the measurement. 図 29 shows the circuit used for measuring the on-leakage current on each signal path, denoted by $I_{DA(ON)}$ and $I_{DB(ON)}$. The absolute difference between these two currents is defined as the differential on-leakage current, denoted by $I_{DL(ON)}$.

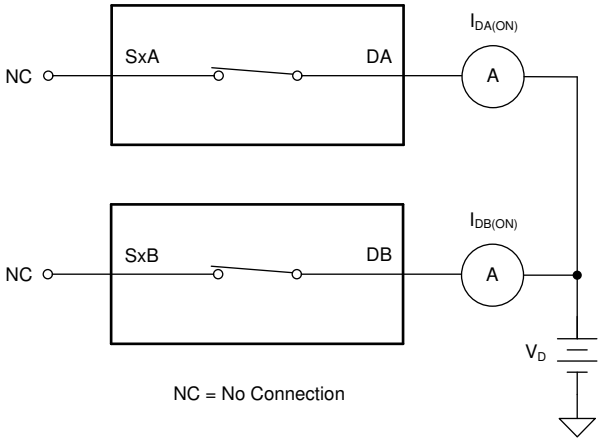

図 29. Differential On-Leakage Measurement Setup

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7.1.5 Transition Time

Transition time is defined as the time taken by the output of the MUX36xxx to rise or fall to 90% of the transition after the digital address signal has fallen or risen to 50% of the transition. 図 30 shows the setup used to measure transition time, denoted by the symbol t_t.

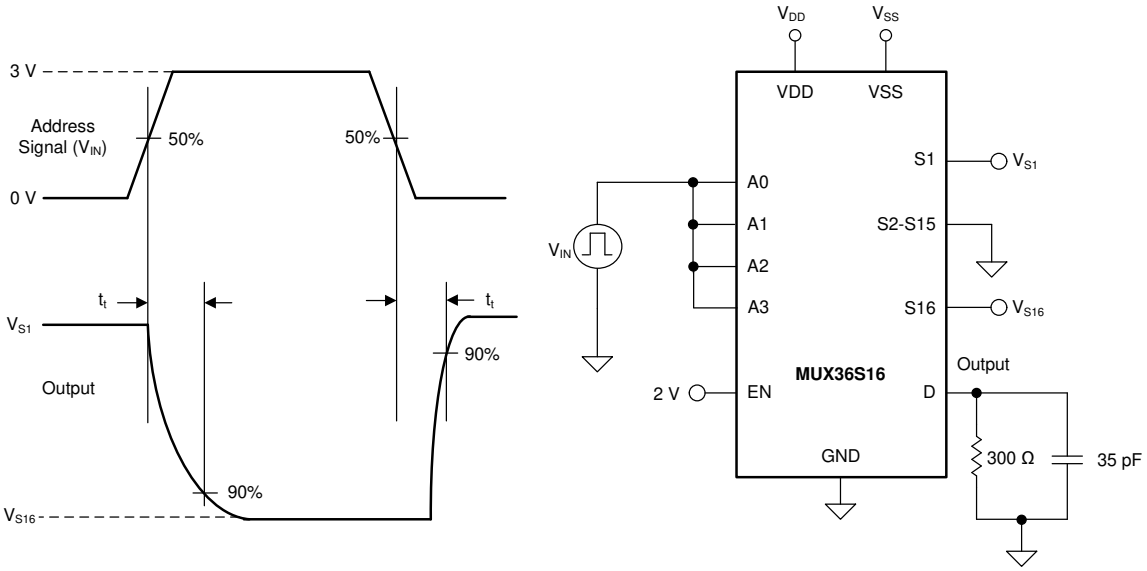

図 30. Transition-Time Measurement Setup

7.1.6 Break-Before-Make Delay

Break-before-make delay is a safety feature that prevents two inputs from connecting when the MUX36xxx is switching. The MUX36xxx output first breaks from the ON-state switch before making the connection with the next ON-state switch. The time delay between the *break* and the *make* is known as break-before-make delay. 図 31 shows the setup used to measure break-before-make delay, denoted by the symbol t_{BBM}.

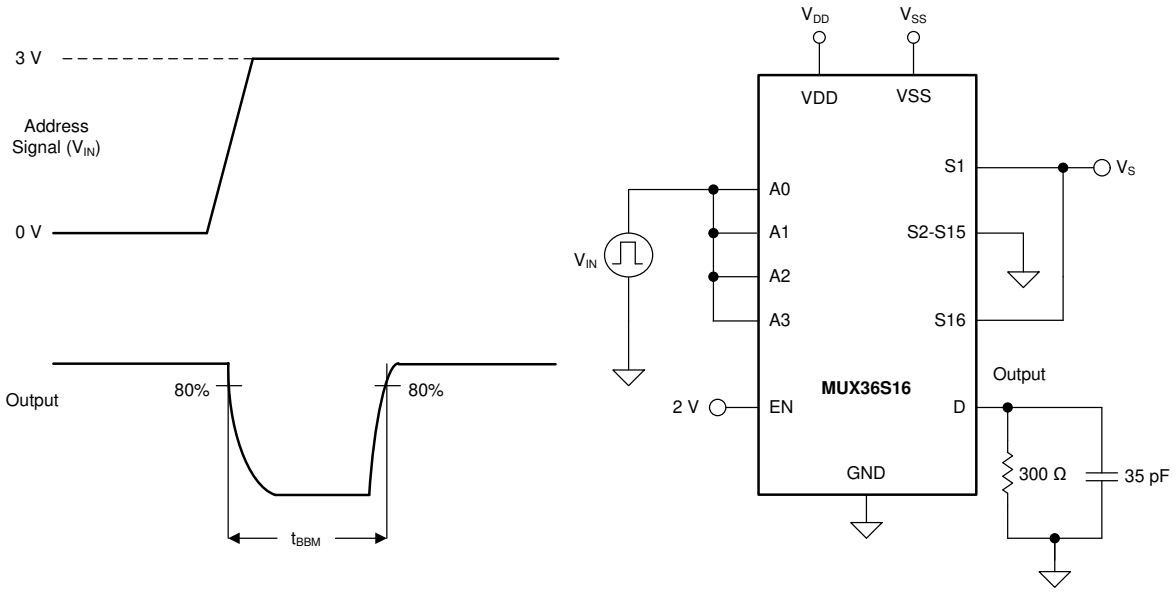

図 31. Break-Before-Make Delay Measurement Setup

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7.1.7 Turn-On and Turn-Off Time

Turn-on time is defined as the time taken by the output of the MUX36xxx to rise to 90% final value after the enable signal has risen to 50% final value. 図 32 shows the setup used to measure turn-on time. Turn-on time is denoted by the symbol t_{ON}.

Turn off time is defined as the time taken by the output of the MUX36xxx to fall to 10% initial value after the enable signal has fallen to 50% initial value. 図 32 shows the setup used to measure turn-off time. Turn-off time is denoted by the symbol t_{OFF}.

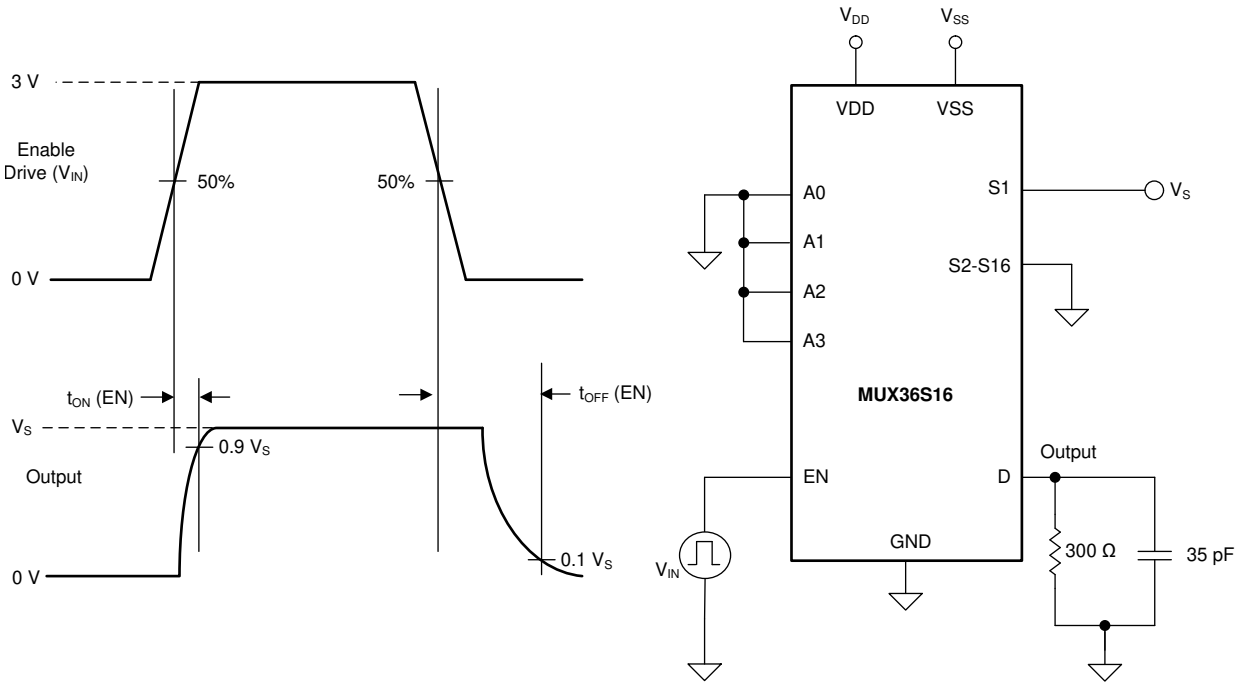

図 32. Turn-On and Turn-Off Time Measurement Setup

7.1.8 Charge Injection

The MUX36xxx have a simple transmission-gate topology. Any mismatch in capacitance between the NMOS and PMOS transistors results in a charge injected into the drain or source during the falling or rising edge of the gate signal. The amount of charge injected into the source or drain of the device is known as charge injection, and is denoted by the symbol Q_{INJ}. 図 33 shows the setup used to measure charge injection.

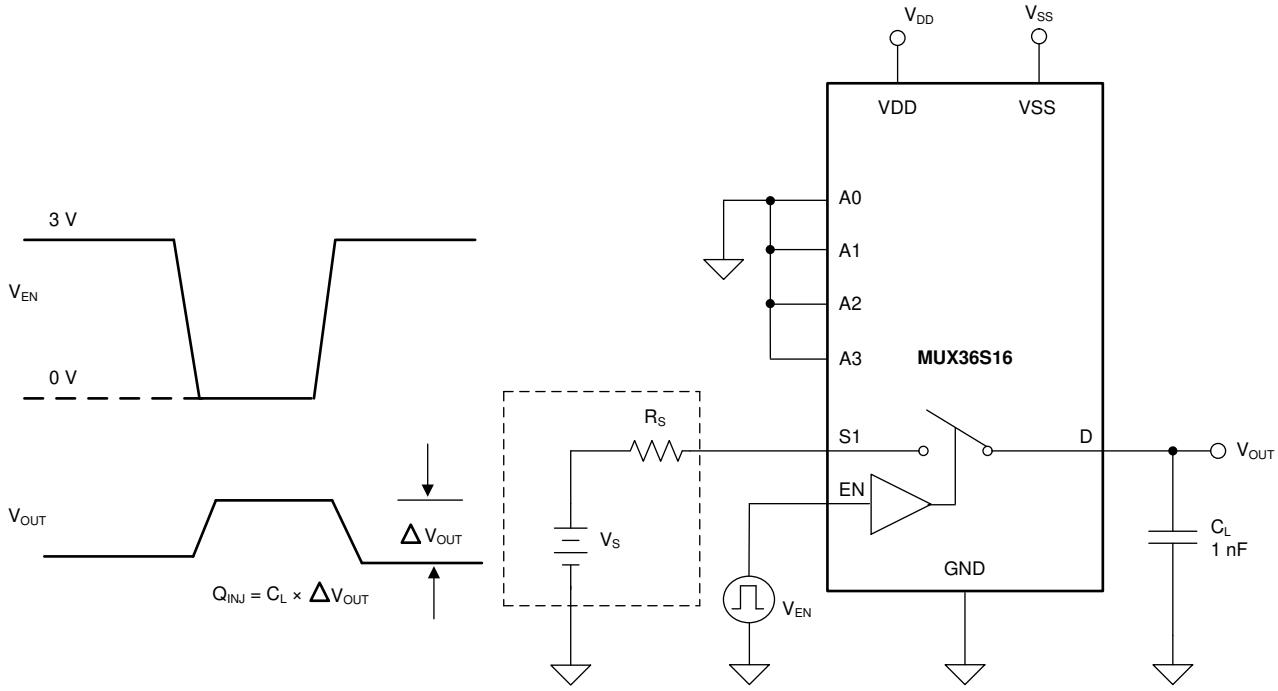

図 33. Charge-Injection Measurement Setup

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7.1.9 Off Isolation

Off isolation is defined as the voltage at the drain pin (D, DA, or DB) of the MUX36xxx when a 1-V_{RMS} signal is applied to the source pin (Sx, SxA, or SxB) of an off-channel. 図 34 shows the setup used to measure off isolation. Use 式 2 to compute off isolation.

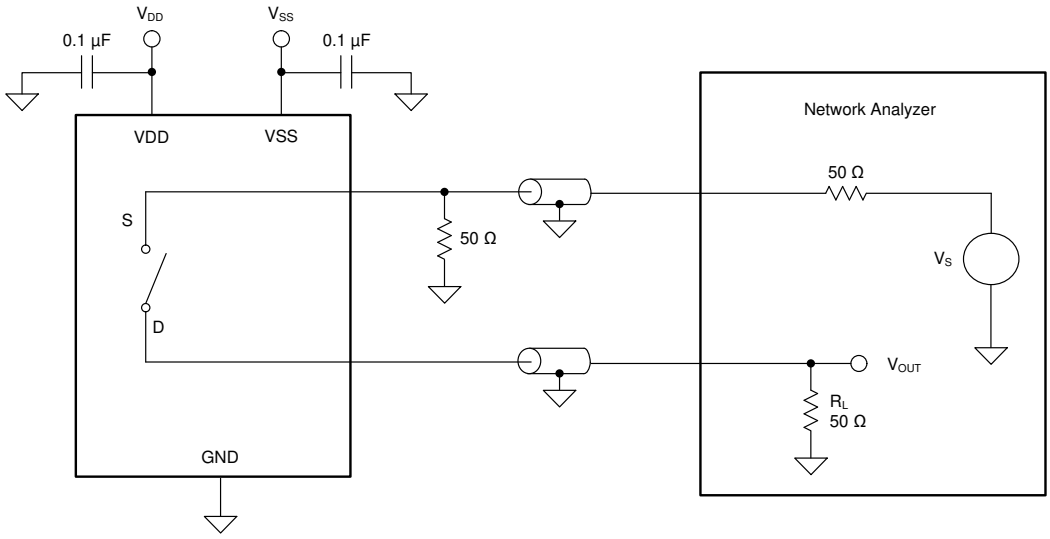

図 34. Off Isolation Measurement Setup

$$\text{Off Isolation} = 20 \cdot \text{Log}\left(\frac{V_{OUT}}{V_S}\right) \quad (2)$$

7.1.10 Channel-to-Channel Crosstalk

Channel-to-channel crosstalk is defined as the voltage at the source pin (Sx, SxA, or SxB) of an off-channel, when a 1-V_{RMS} signal is applied at the source pin of an on-channel. 図 35 shows the setup used to measure channel-to-channel crosstalk. Use 式 3 to compute, channel-to-channel crosstalk.

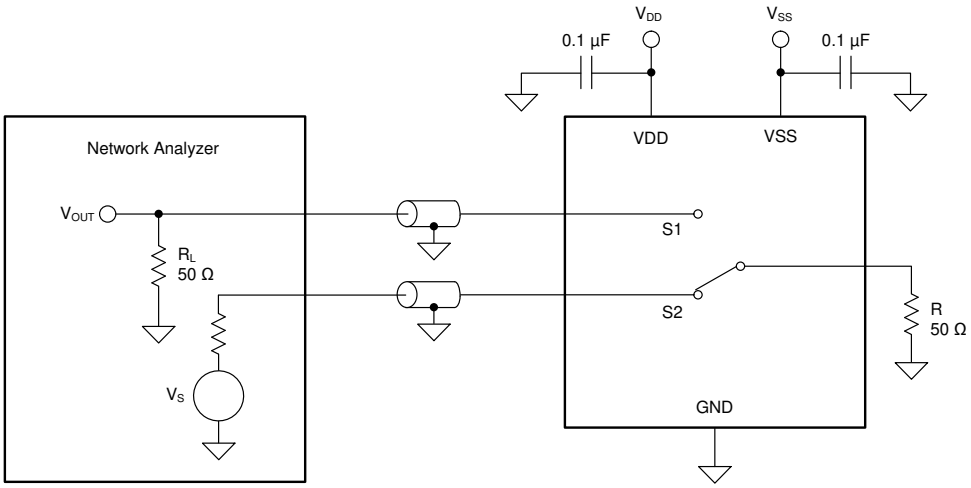

図 35. Channel-to-Channel Crosstalk Measurement Setup

$$\text{Channel-to-Channel Crosstalk} = 20 \cdot \text{Log}\left(\frac{V_{OUT}}{V_S}\right) \quad (3)$$

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7.1.11 Bandwidth

Bandwidth is defined as the range of frequencies that are attenuated by less than 3 dB when the input is applied to the source pin of an on-channel, and the output measured at the drain pin of the MUX36xxx. 図 36 shows the setup used to measure bandwidth of the mux. Use 式 4 to compute the attenuation.

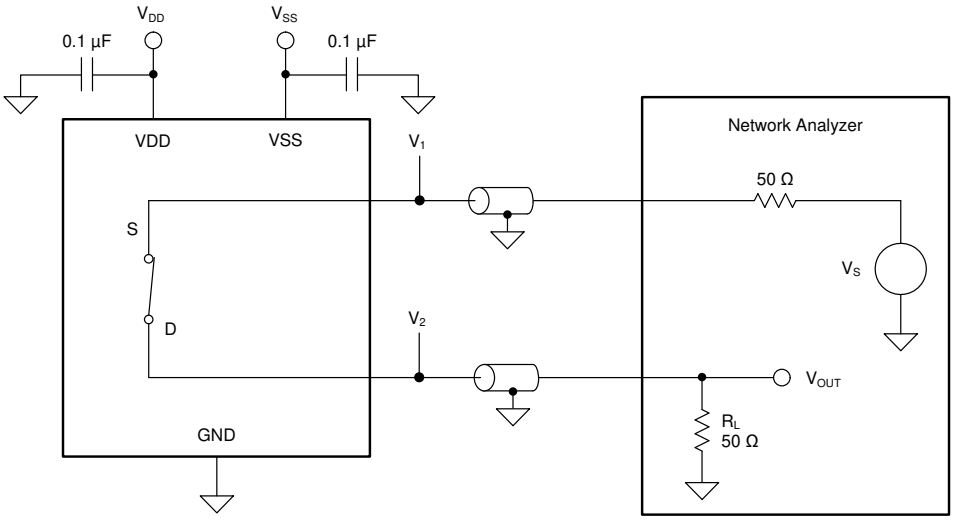

図 36. Bandwidth Measurement Setup

$$\text{Attenuation} = 20 \cdot \text{Log}\left(\frac{V_2}{V_1}\right) \tag{4}$$

7.1.12 THD + Noise

The total harmonic distortion (THD) of a signal is a measurement of the harmonic distortion, and is defined as the ratio of the sum of the powers of all harmonic components to the power of the fundamental frequency at the mux output. The on-resistance of the MUX36xxx varies with the amplitude of the input signal and results in distortion when the drain pin is connected to a low-impedance load. Total harmonic distortion plus noise is denoted as THD+N. 図 37 shows the setup used to measure THD+N of the MUX36xxx.

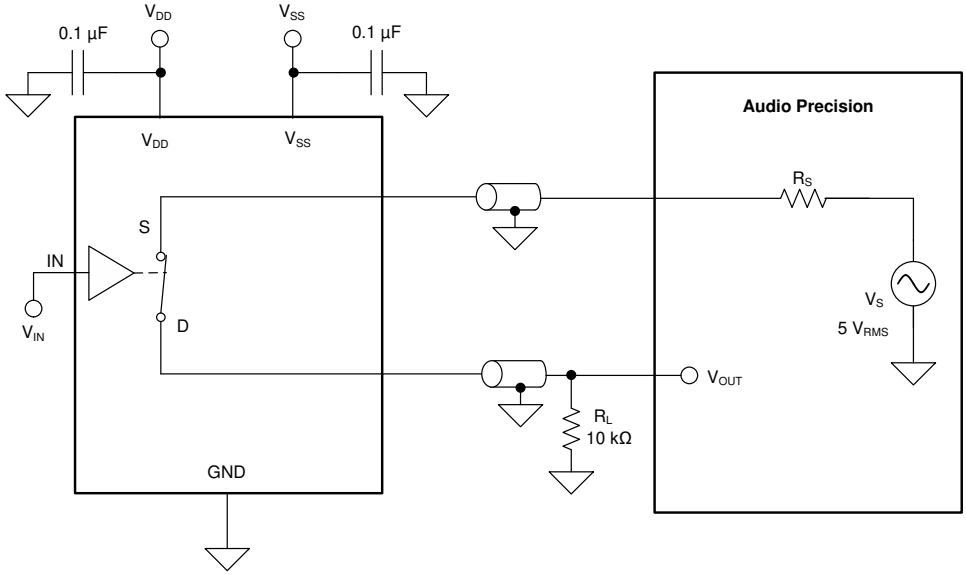

図 37. THD+N Measurement Setup

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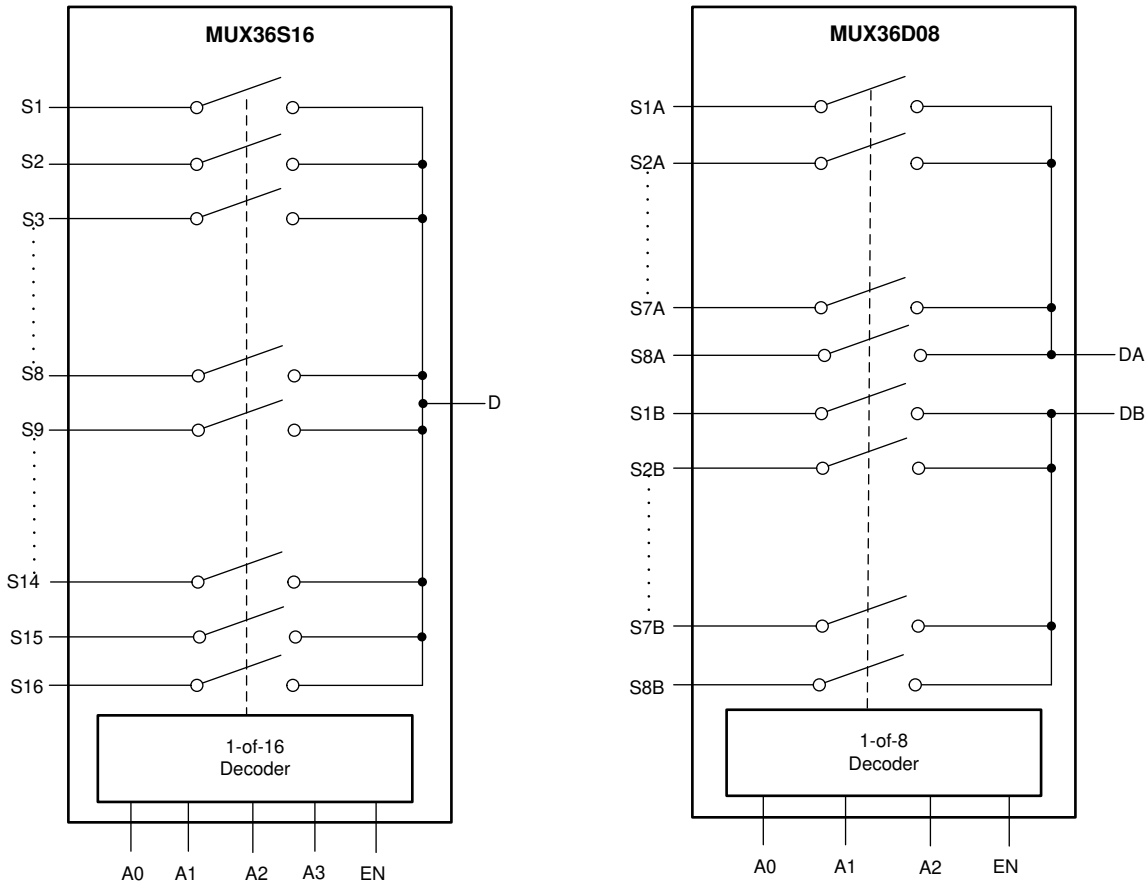
8 Detailed Description

8.1 Overview

The MUX36xxx are a family of analog multiplexers. The *Functional Block Diagram* section provides a top-level block diagram of both the MUX36S16 and MUX36D08. The MUX36S16 is a 16-channel, single-ended, analog mux. The MUX36D08 is an 8-channel, differential or dual 8:1, single-ended, analog mux. Each channel is turned on or turned off based on the state of the address lines and enable pin.

8.2 Functional Block Diagram



8.3 Feature Description

8.3.1 Ultralow Leakage Current

The MUX36xxx provide extremely low on- and off-leakage currents. The MUX36xxx are capable of switching signals from high source-impedance inputs into a high input-impedance op amp with minimal offset error because of the ultra-low leakage currents. 図 38 shows typical leakage currents of the MUX36xxx versus temperature.

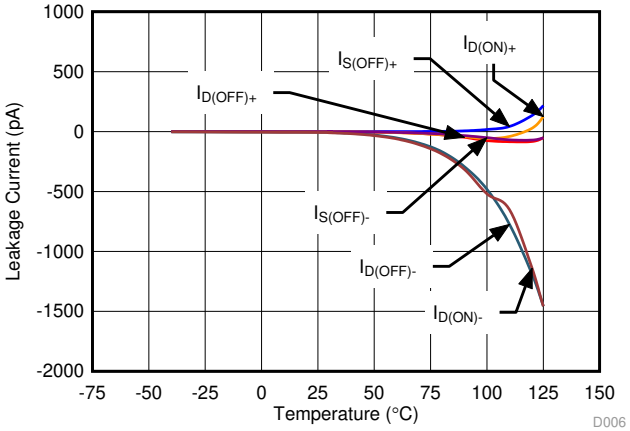


図 38. Leakage Current vs Temperature

8.3.2 Ultralow Charge Injection

The MUX36xxx have a simple transmission gate topology, as shown in 図 39. Any mismatch in the stray capacitance associated with the NMOS and PMOS causes an output level change whenever the switch is opened or closed.

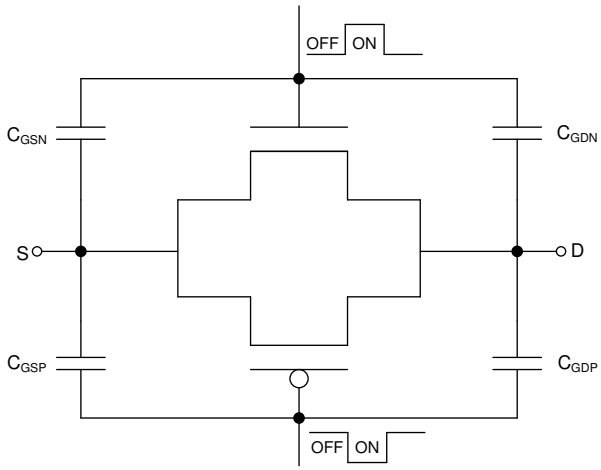


図 39. Transmission Gate Topology

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Feature Description (continued)

The MUX36xxx have special charge-injection cancellation circuitry that reduces the source-to-drain charge injection to as low as 0.31 pC at V_S = 0 V, and ±0.9 pC in the full signal range, as shown in 図 40.

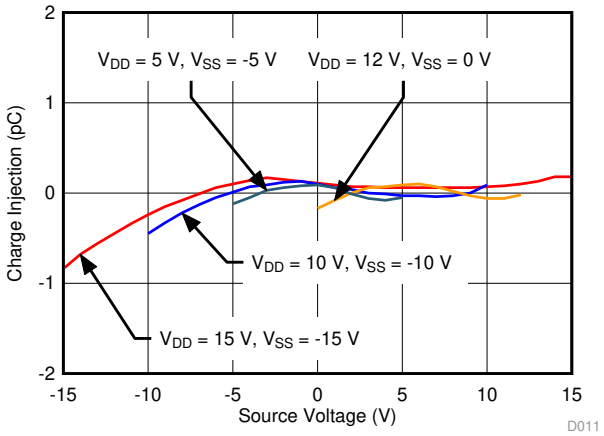

図 40. Source-to-Drain Charge Injection

The drain-to-source charge injection becomes important when the device is used as a demultiplexer (demux), where D becomes the input and Sx becomes the output. 図 41 shows the drain-to-source charge injection across the full signal range.

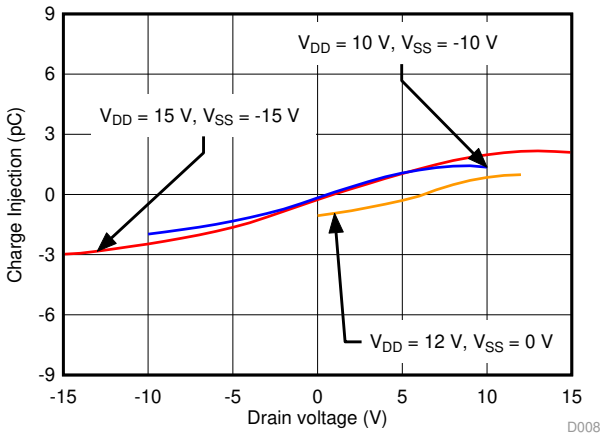

図 41. Drain-to-Source Charge Injection

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Feature Description (continued)

8.3.3 Bidirectional Operation

The MUX36xxx are operable as both a mux and demux. The source (Sx, SxA, SxB) and drain (D, DA, DB) pins of the MUX36xxx are used either as input or output. Each MUX36xxx channel has very similar characteristics in both directions.

8.3.4 Rail-to-Rail Operation

The valid analog signal for the MUX36xxx ranges from V_{SS} to V_{DD}. The input signal to the MUX36xxx swings from V_{SS} to V_{DD} without any significant degradation in performance. The on-resistance of the MUX36xxx varies with input signal, as shown in 図 42

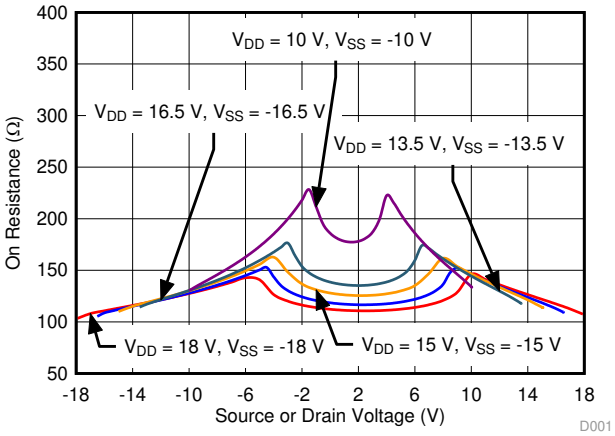

図 42. On-resistance vs Source or Drain Voltage

8.4 Device Functional Modes

When the EN pin of the MUX36xxx is pulled high, one of the switches is closed based on the state of the address lines. When the EN pin is pulled low, all the switches are in an open state irrespective of the state of the address lines. The EN pin can be connected to V_{DD} (as high as 36 V).

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9 Application and Implementation

注

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The MUX36xxx family offers outstanding input/output leakage currents and ultra-low charge injection. These devices operate up to 36 V, and offer true rail-to-rail input and output. The on-capacitance of the MUX36xxx is very low. These features makes the MUX36xxx a family of precision, robust, high-performance analog multiplexer for high-voltage, industrial applications.

9.2 Typical Application

図 43 shows a 16-bit, differential, 8-channel, multiplexed, data-acquisition system. This example is typical in industrial applications that require low distortion and a high-voltage differential input. The circuit uses the ADS8864, a 16-bit, 400-kSPS successive-approximation-resistor (SAR) analog-to-digital converter (ADC), along with a precision, high-voltage, signal-conditioning front end, and a 4-channel differential mux. This TI Precision Design details the process for optimizing the precision, high-voltage, front-end drive circuit using the MUX36D08, OPA192 and OPA140 to achieve excellent dynamic performance and linearity with the ADS8864.

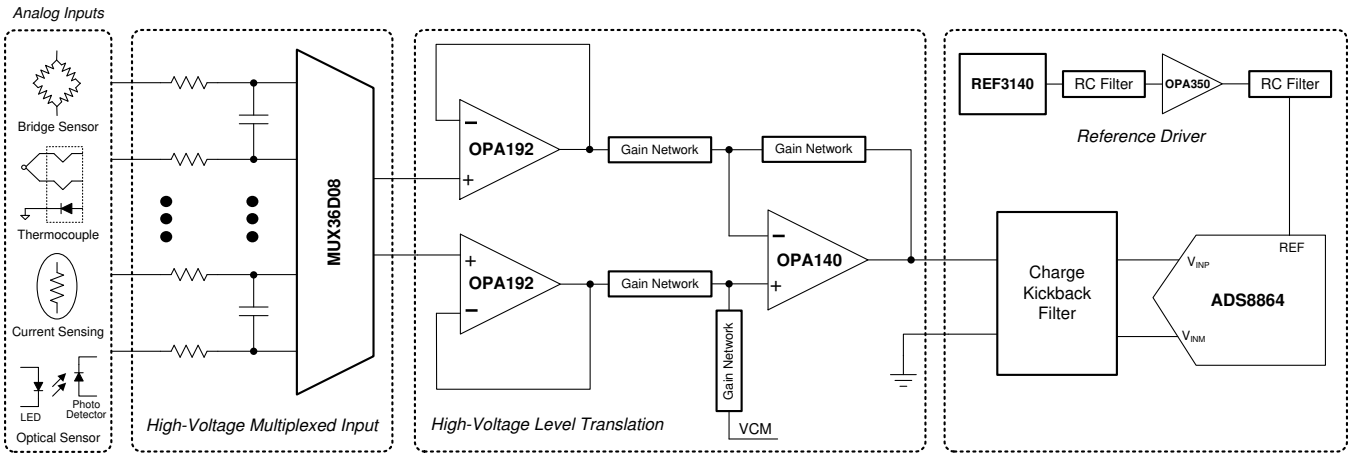

図 43. 16-Bit Precision Multiplexed Data-Acquisition System for High-Voltage Inputs With Lowest Distortion

9.2.1 Design Requirements

The primary objective is to design a ±20 V, differential, 8-channel, multiplexed, data-acquisition system with lowest distortion using the 16-bit ADS8864 at a throughput of 400 kSPS for a 10-kHz, full-scale, pure, sine-wave input. The design requirements for this block design are:

- System supply voltage: ±15 V
- ADC supply voltage: 3.3 V
- ADC sampling rate: 400 kSPS
- ADC reference voltage (REFP): 4.096 V
- System input signal: A high-voltage differential input signal with a peak amplitude of 20 V and frequency (f_{IN}) of 10 kHz are applied to each differential input of the mux.

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Typical Application (continued)

9.2.2 Detailed Design Procedure

The purpose of this precision design is to design an optimal, high-voltage, multiplexed, data-acquisition system for highest system linearity and fast settling. The overall system block diagram is illustrated in 図 43. The circuit is a multichannel, data-acquisition signal chain consisting of an input low-pass filter, mux, mux output buffer, attenuating SAR ADC driver, and the reference driver. The architecture allows fast sampling of multiple channels using a single ADC, providing a low-cost solution. This design systematically approaches each analog circuit block to achieve a 16-bit settling for a full-scale input stage voltage and linearity for a 10-kHz sinusoidal input signal at each input channel. Detailed design considerations and component selection procedure can be found in the TI Precision Design TIPD151, *16-Bit, 400-kSPS, 4-Channel Multiplexed Data-Acquisition System for High-Voltage Inputs with Lowest Distortion*.

9.2.3 Application Curve

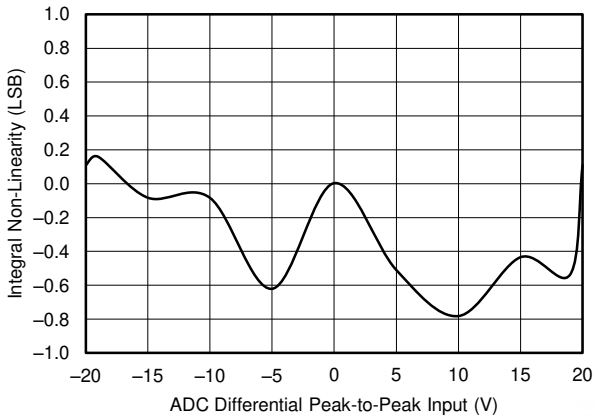

図 44. ADC 16-Bit Linearity Error for the Multiplexed Data-Acquisition Block

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10 Power Supply Recommendations

The MUX36xxx operates across a wide supply range of ±5 V to ±18 V (10 V to 36 V in single-supply mode). The devices also perform well with unsymmetric supplies such as V_{DD} = 12 V and V_{SS}= –5 V. For reliable operation, use a supply decoupling capacitor ranging between 0.1 µF to 10 µF at both the VDD and VSS pins to ground.

The on-resistance of the MUX36xxx varies with supply voltage, as illustrated in 図 45

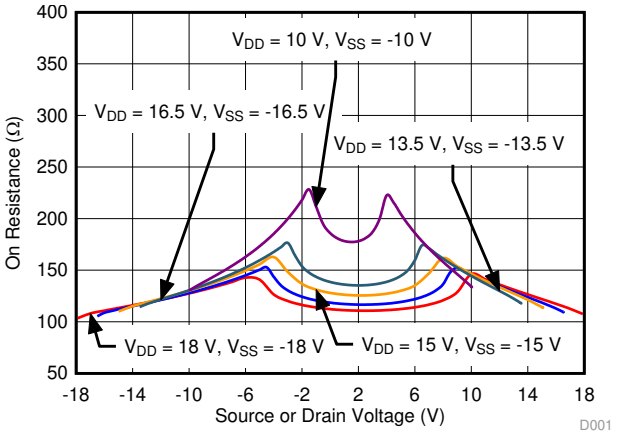

図 45. On-Resistance Variation With Supply and Input Voltage

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11 Layout

11.1 Layout Guidelines

図 46 illustrates an example of a PCB layout with the MUX36S16IPW, and 図 47 illustrates an example of a PCB layout with MUX36D08IPW.

Some key considerations are:

1. Decouple the VDD and VSS pins with a 0.1-µF capacitor, placed as close to the pin as possible. Make sure that the capacitor voltage rating is sufficient for the V_{DD} and V_{SS} supplies.
2. Keep the input lines as short as possible. In case of the differential signal, make sure the A inputs and B inputs are as symmetric as possible.
3. Use a solid ground plane to help distribute heat and reduce electromagnetic interference (EMI) noise pickup.
4. Do not run sensitive analog traces in parallel with digital traces. Avoid crossing digital and analog traces if possible, and only make perpendicular crossings when necessary.

11.2 Layout Example

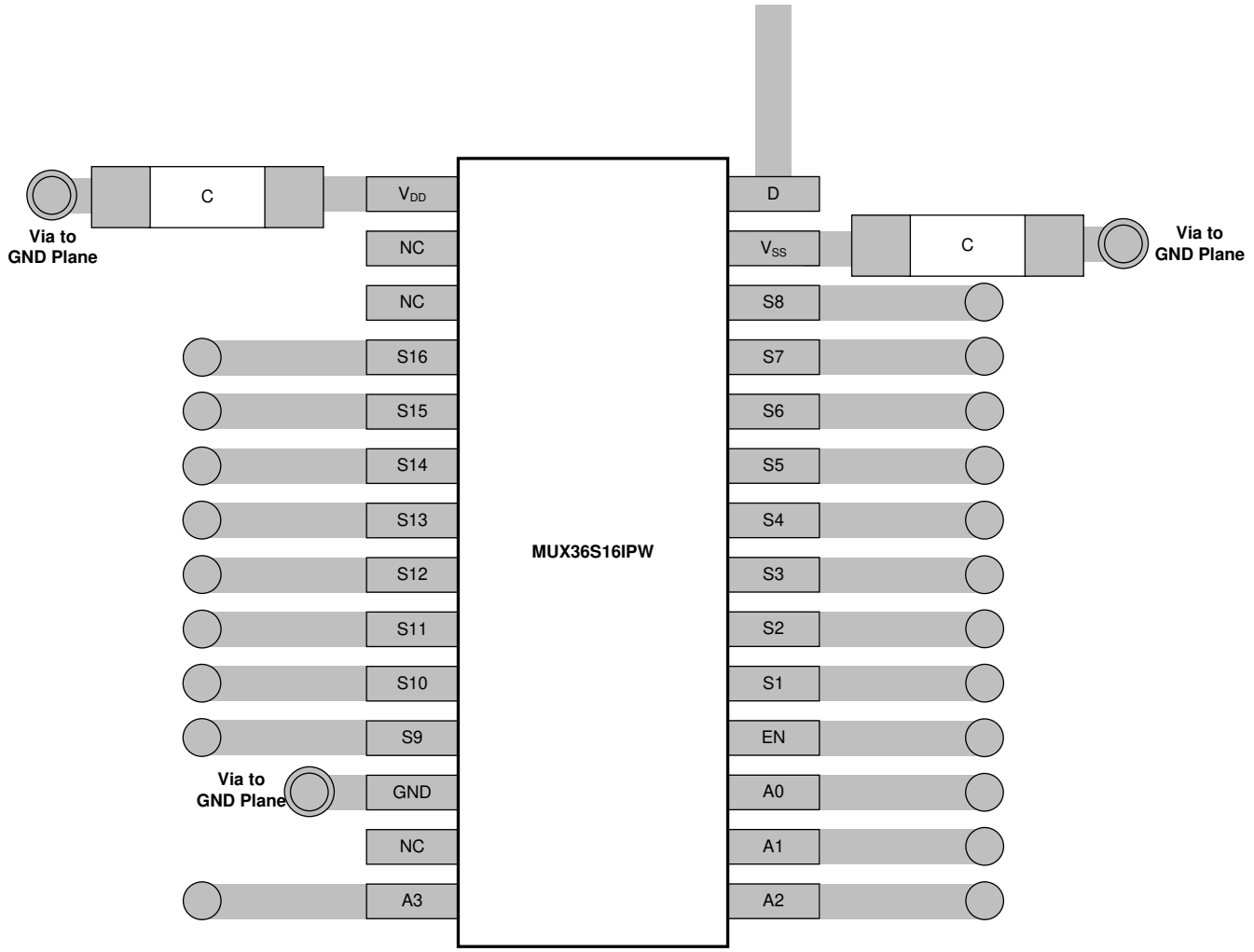

図 46. MUX36S16IPW Layout Example

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Layout Example (continued)

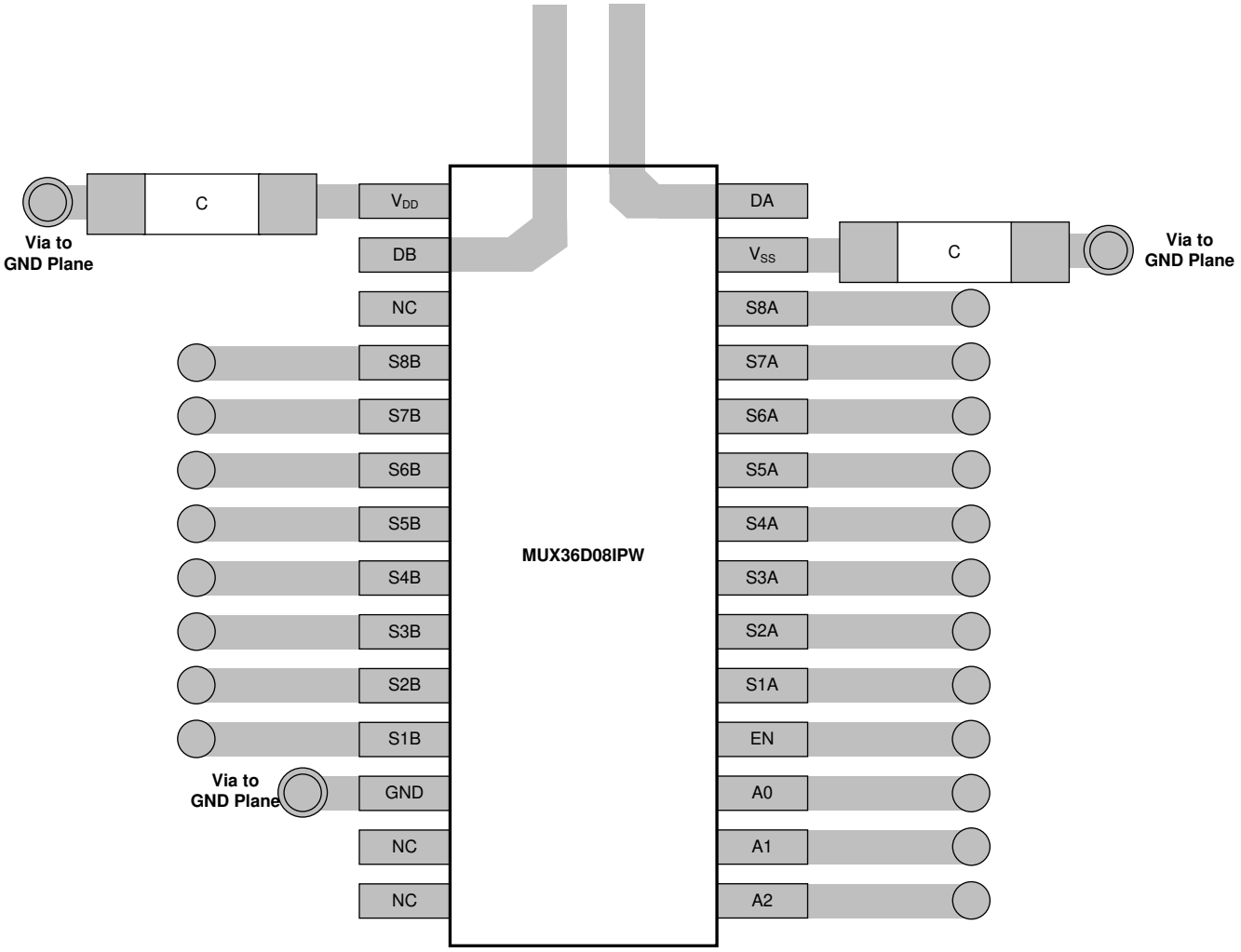

図 47. MUX36D08IPW Layout Example

12 デバイスおよびドキュメントのサポート

12.1 ドキュメントのサポート

12.1.1 関連資料

関連資料については、以下を参照してください。

- 『ADS8864 16ビット、400kSPS、シリアル・インターフェイス、microPower、小型、シングルエンド入力、SARアナログ・デジタル・コンバータ』(SBAS572)
- 『OPAx192 36V、高精度、レール・ツー・レール入力/出力、低オフセット電圧、e-trim低入力バイアス電流オペアンプ』(SBOS620)
- 『OPAx140高精度、低ノイズ、レール・ツー・レール出力、11MHz JFETオペアンプ』(SBOS498)

12.2 関連リンク

次の表に、クイック・アクセス・リンクを示します。カテゴリには、技術資料、サポートおよびコミュニティ・リソース、ツールとソフトウェア、およびご注文へのクイック・アクセスが含まれます。

表 3. 関連リンク

製品	プロダクト・フォルダ	ご注文はこちら	技術資料	ツールとソフトウェア	サポートとコミュニティ
MUX36S16	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック
MUX36D08	ここをクリック	ここをクリック	ここをクリック	ここをクリック	ここをクリック

12.3 ドキュメントの更新通知を受け取る方法

ドキュメントの更新についての通知を受け取るには、ti.comのデバイス製品フォルダを開いてください。右上の「アラートを受け取る」をクリックして登録すると、変更されたすべての製品情報に関するダイジェストを毎週受け取れます。変更の詳細については、修正されたドキュメントに含まれている改訂履歴をご覧ください。

12.4 コミュニティ・リソース

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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すべての集積回路は、適切なESD保護方法を用いて、取扱いと保存を行うようにして下さい。

静電気放電はわずかな性能の低下から完全なデバイスの故障に至るまで、様々な損傷を与えます。高精度の集積回路は、損傷に対して敏感であり、極めてわずかなパラメータの変化により、デバイスに規定された仕様に適合しなくなる場合があります。

12.7 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 メカニカル、パッケージ、および注文情報

以降のページには、メカニカル、パッケージ、および注文に関する情報が記載されています。この情報は、そのデバイスについて利用可能な最新のデータです。このデータは予告なく変更されることがあり、ドキュメントが改訂される場合もあります。本データシートのブラウザ版を使用されている場合は、画面左側の説明をご覧ください。

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
MUX36D08IDWR	ACTIVE	SOIC	DW	28	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36D08D	Samples
MUX36D08IPW	ACTIVE	TSSOP	PW	28	50	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36D080A	Samples
MUX36D08IPWR	ACTIVE	TSSOP	PW	28	2000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36D080A	Samples
MUX36D08IRSNR	ACTIVE	QFN	RSN	32	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MUX 36D08	Samples
MUX36D08IRTVR	ACTIVE	WQFN	RTV	32	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MUX 36D08	Samples
MUX36S16IDWR	ACTIVE	SOIC	DW	28	1000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36S16DA	Samples
MUX36S16IPW	ACTIVE	TSSOP	PW	28	50	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36S160A	Samples
MUX36S16IPWR	ACTIVE	TSSOP	PW	28	2000	RoHS & Green	NIPDAU	Level-3-260C-168 HR	-40 to 125	MUX36S160A	Samples
MUX36S16IRSNR	ACTIVE	QFN	RSN	32	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MUX 36S16	Samples
MUX36S16IRTVR	ACTIVE	WQFN	RTV	32	3000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 125	MUX 36S16	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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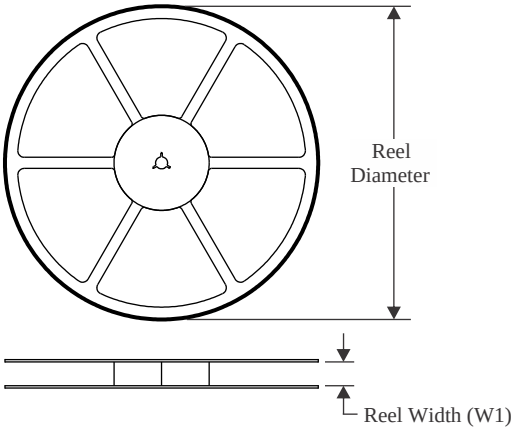
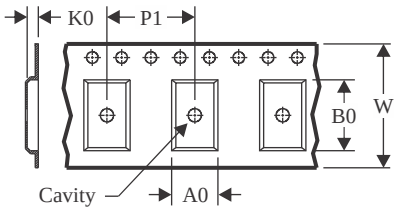
TAPE AND REEL INFORMATION

REEL DIMENSIONS

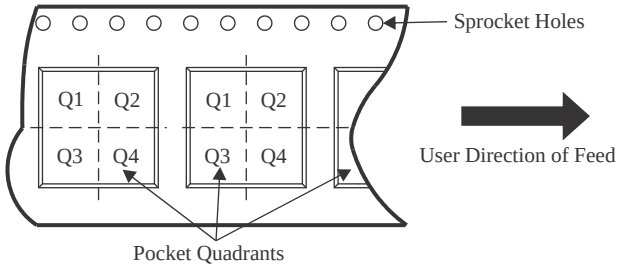


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

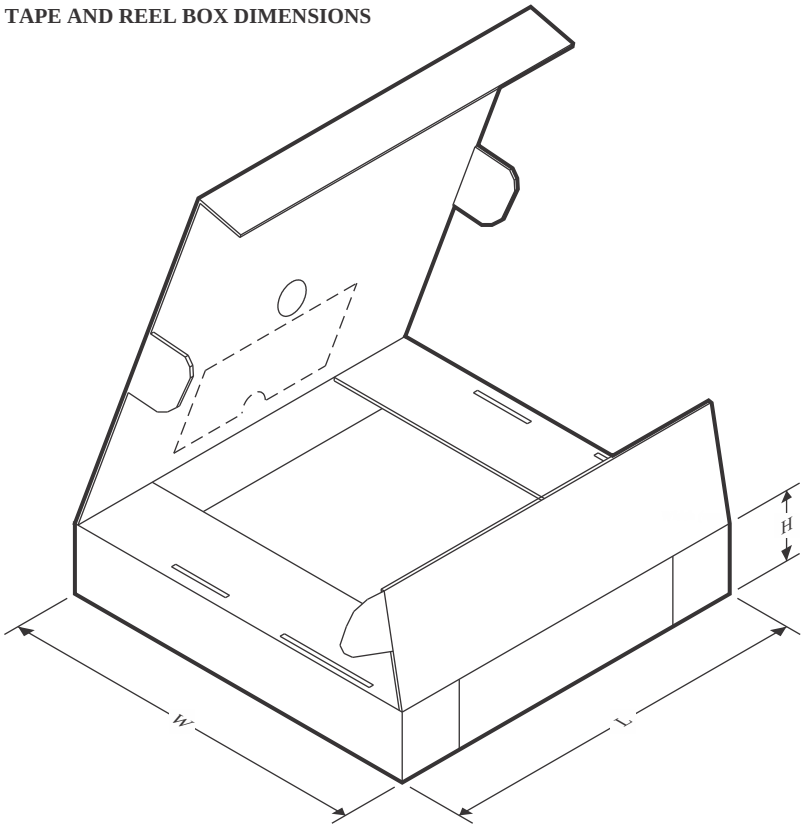
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
MUX36D08IDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MUX36D08IPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MUX36D08IPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MUX36D08IRSNR	QFN	RSN	32	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
MUX36D08IRTVR	WQFN	RTV	32	3000	330.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2
MUX36S16IDWR	SOIC	DW	28	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1
MUX36S16IPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MUX36S16IPWR	TSSOP	PW	28	2000	330.0	16.4	6.9	10.2	1.8	12.0	16.0	Q1
MUX36S16IRSNR	QFN	RSN	32	3000	330.0	12.4	4.25	4.25	1.15	8.0	12.0	Q2
MUX36S16IRTVR	WQFN	RTV	32	3000	330.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2

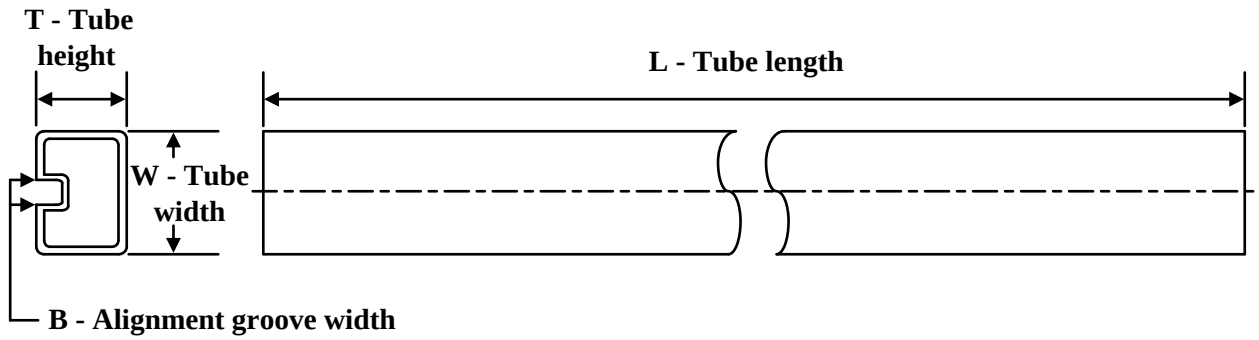
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
MUX36D08IDWR	SOIC	DW	28	1000	350.0	350.0	66.0
MUX36D08IPWR	TSSOP	PW	28	2000	350.0	350.0	43.0
MUX36D08IPWR	TSSOP	PW	28	2000	350.0	350.0	43.0
MUX36D08IRSNR	QFN	RSN	32	3000	367.0	367.0	35.0
MUX36D08IRTVR	WQFN	RTV	32	3000	367.0	367.0	35.0
MUX36S16IDWR	SOIC	DW	28	1000	350.0	350.0	66.0
MUX36S16IPWR	TSSOP	PW	28	2000	350.0	350.0	43.0
MUX36S16IPWR	TSSOP	PW	28	2000	350.0	350.0	43.0
MUX36S16IRSNR	QFN	RSN	32	3000	367.0	367.0	35.0
MUX36S16IRTVR	WQFN	RTV	32	3000	367.0	367.0	35.0

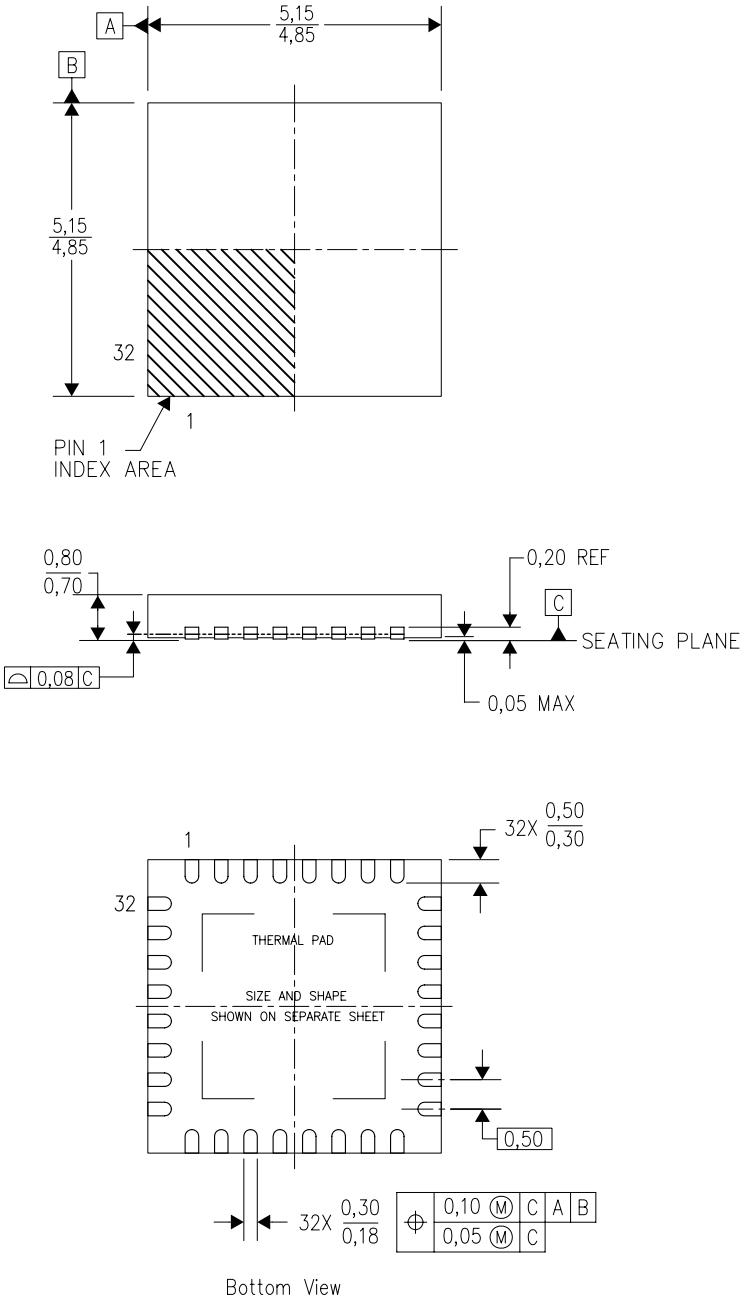
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
MUX36D08IPW	PW	TSSOP	28	50	530	10.2	3600	3.5
MUX36S16IPW	PW	TSSOP	28	50	530	10.2	3600	3.5

RTV (S–PWQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD



4206245/C 10/11

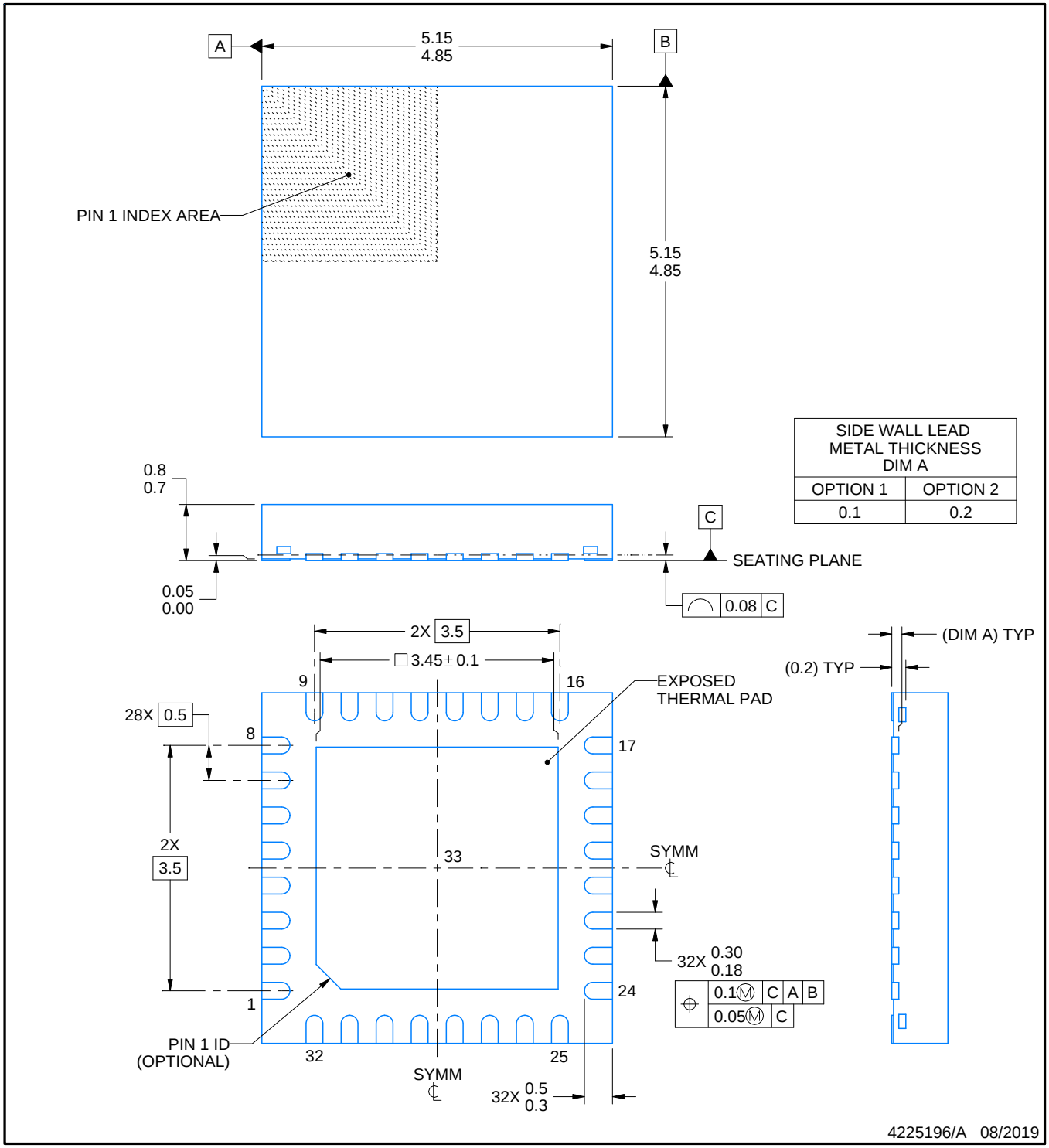
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5–1994.
B. This drawing is subject to change without notice.
C. Quad Flatpack, No–Leads (QFN) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
F. Falls within JEDEC MO–220.

RTV0032E

PACKAGE OUTLINE

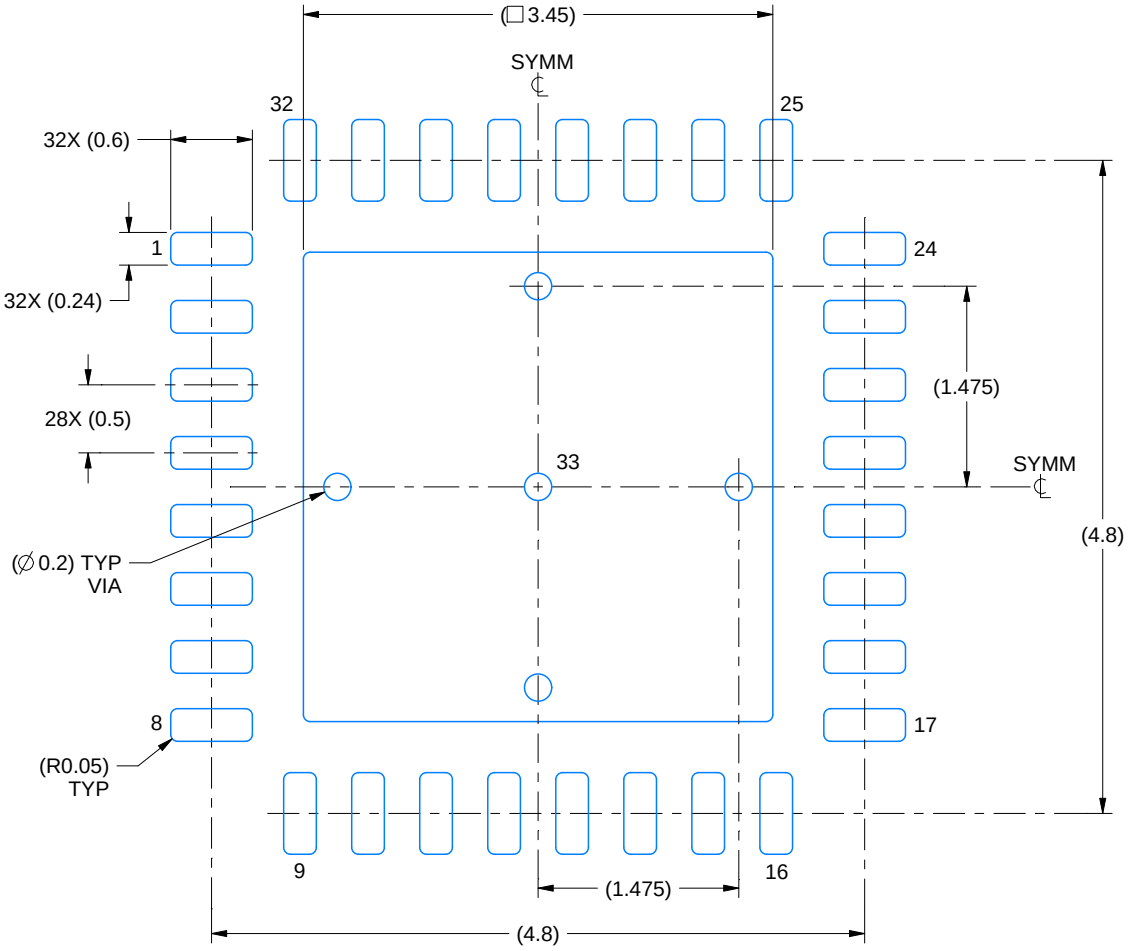
WQFN - 0.8 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

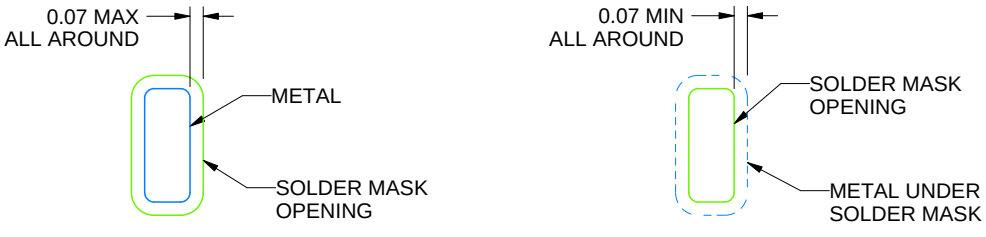


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
SCALE:18X



NON SOLDER MASK
DEFINED
(PREFERRED)

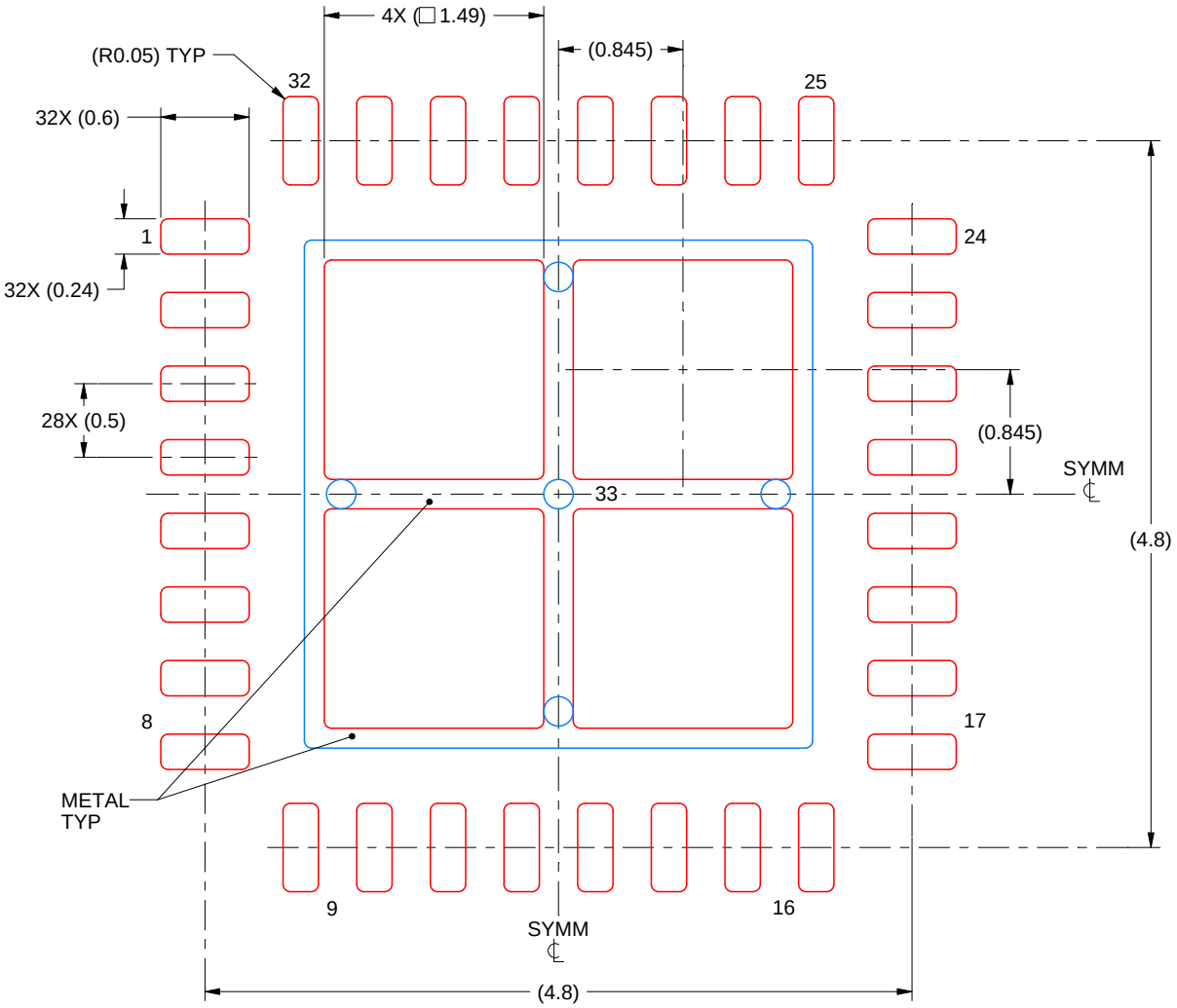
SOLDER MASK
DEFINED

SOLDER MASK DETAILS

4225196/A 08/2019

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

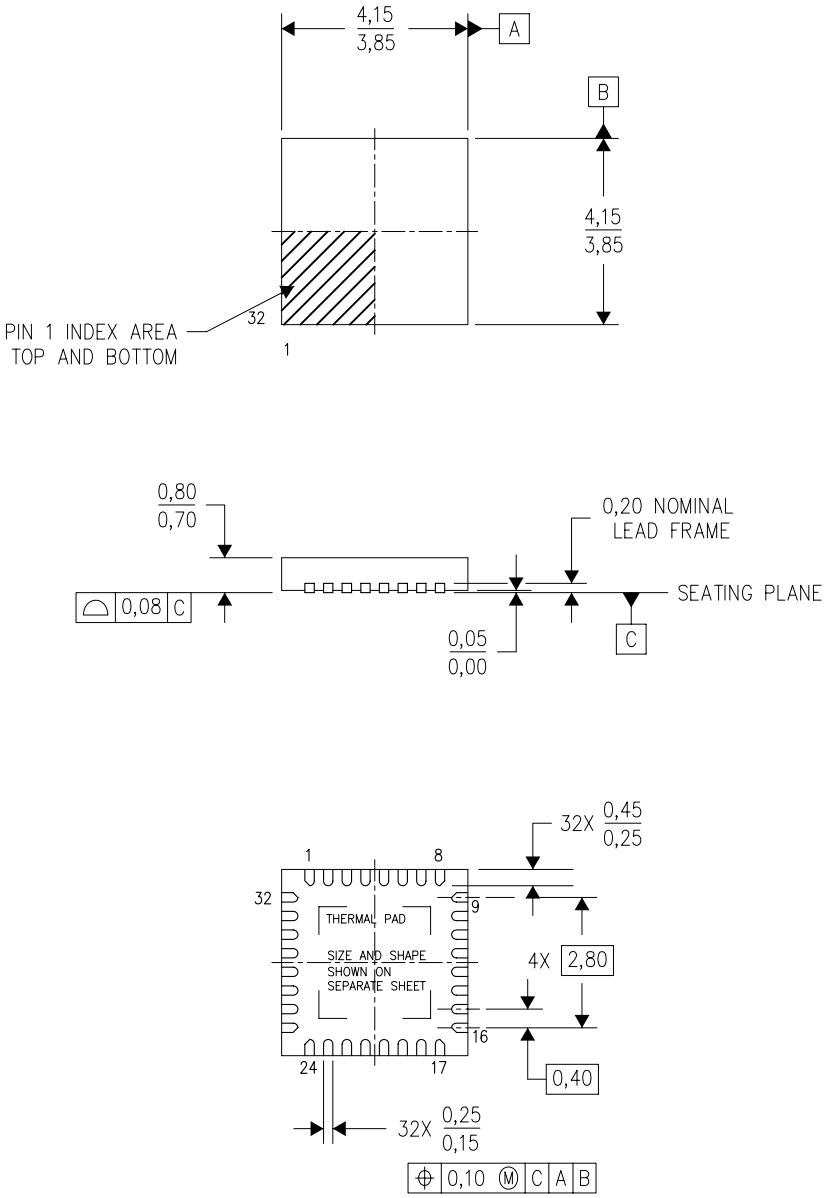
EXPOSED PAD 33:
75% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4225196/A 08/2019

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

RSN (S–PWQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD



4207561/C 08/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No–Lead) Package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

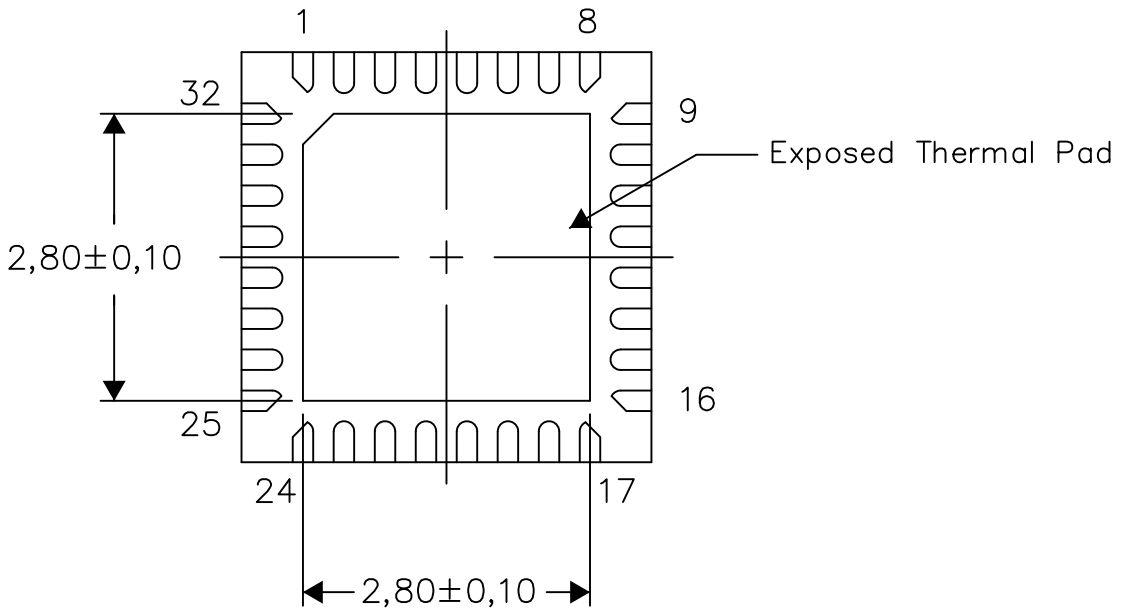
RSN (S–PWQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



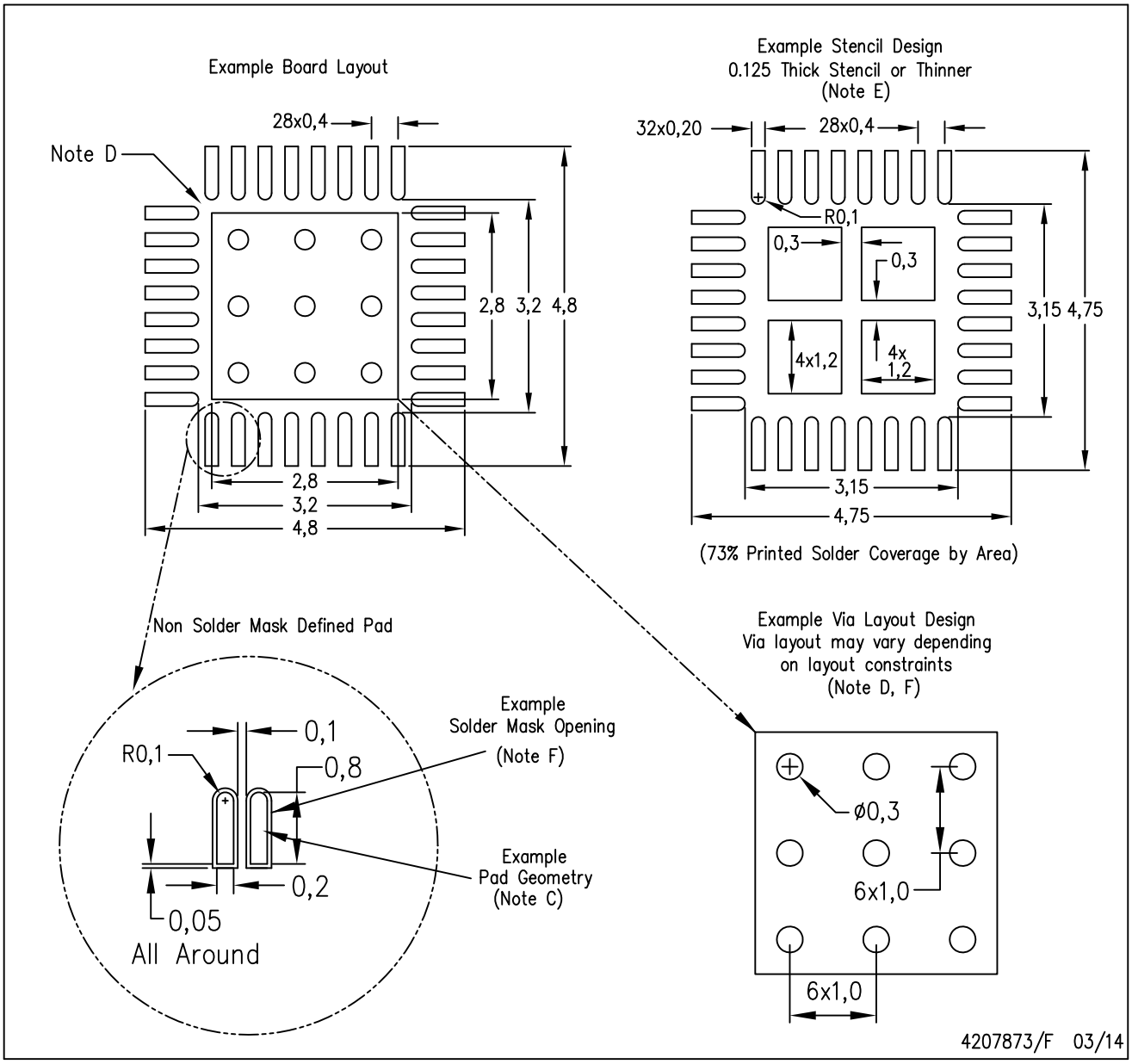
Bottom View

Exposed Thermal Pad Dimensions

4209775–2/F 03/14

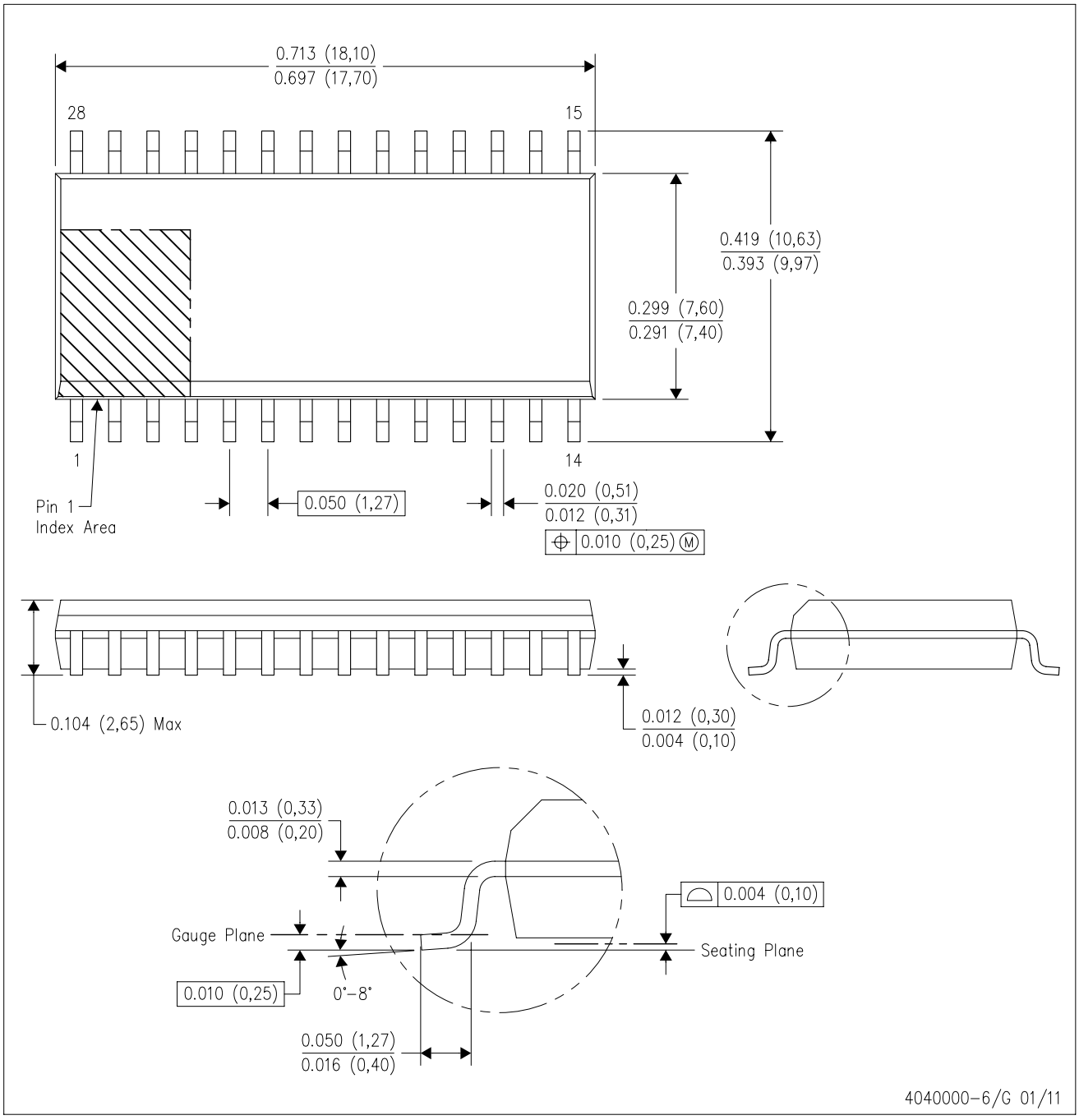
NOTE: All linear dimensions are in millimeters

RSN (S–PWQFN–N32) PLASTIC QUAD FLATPACK NO–LEAD



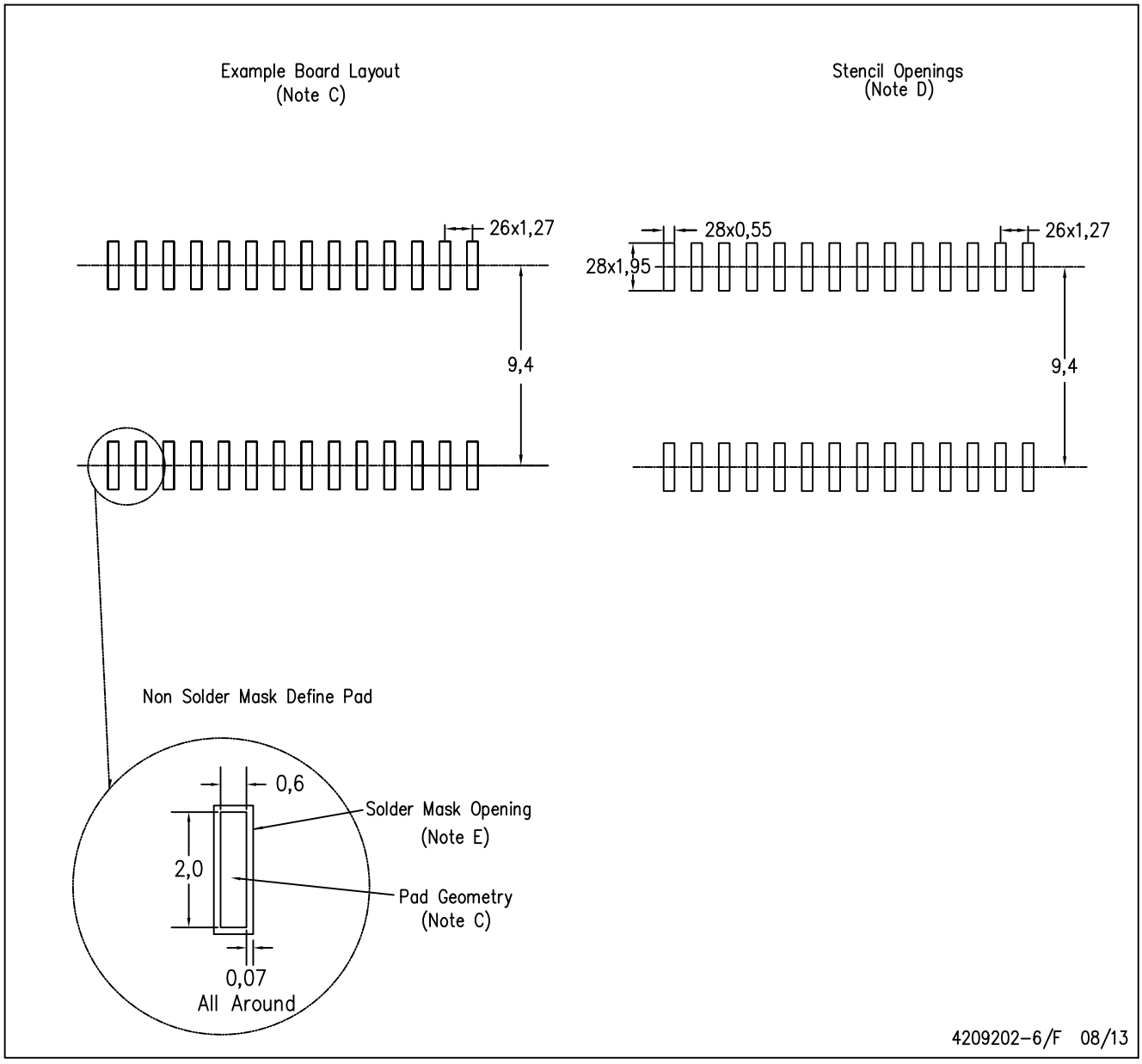
NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat–Pack Packages, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http: //www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for recommended solder mask tolerances and via tenting recommendations for vias placed in the thermal pad.

DW (R–PDSO–G28) PLASTIC SMALL OUTLINE



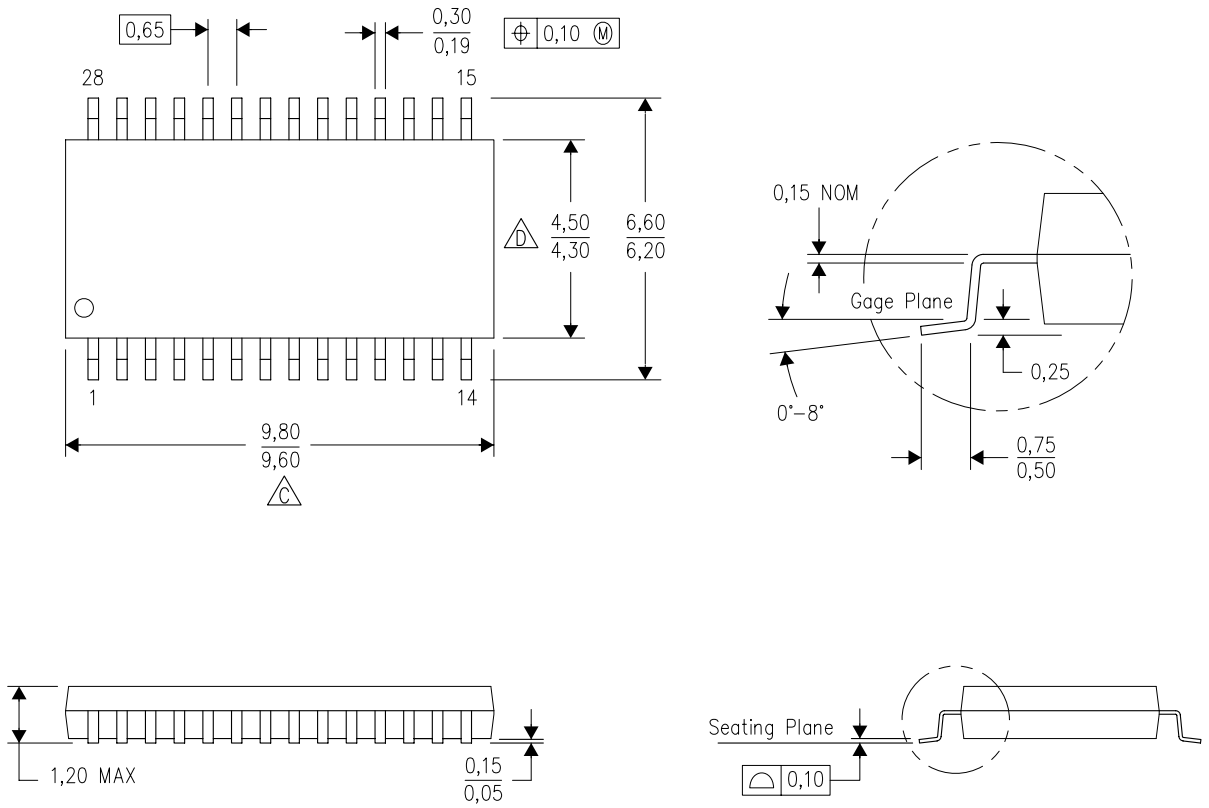
NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AE.

DW (R–PDSO–G28) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

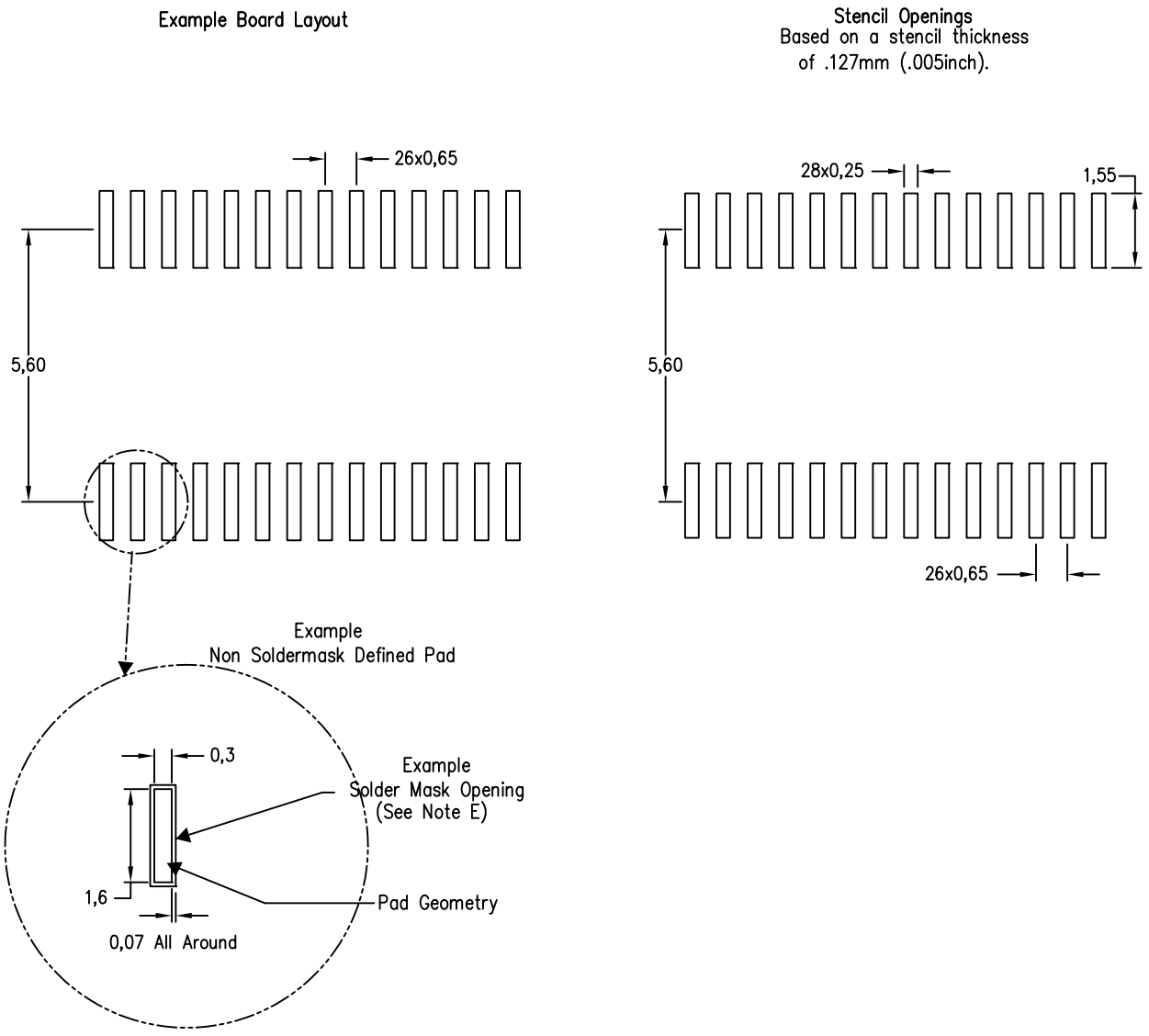
PW (R–PDSO–G28) PLASTIC SMALL OUTLINE



4040064–7/G 02/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
E. Falls within JEDEC MO–153

PW (R–PDSO–G28) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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